
Modeling and Design of Multiwinding Magnetics for High Frequency Power Electronics

Minjie Chen

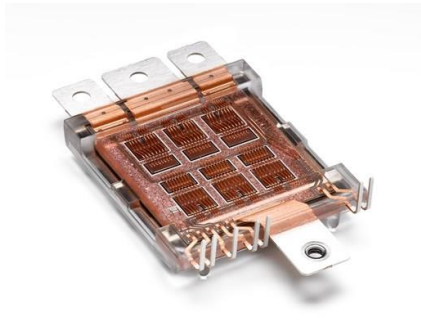
Assistant Professor

Princeton University

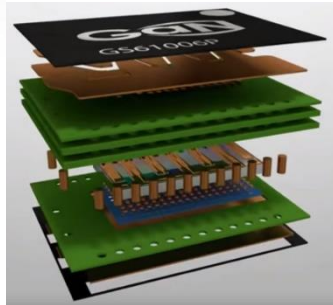
High Frequency Magnetics Workshop, 2020



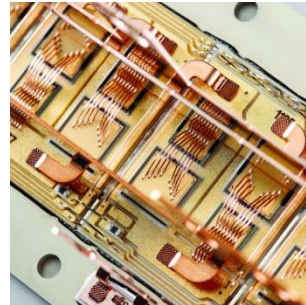
❑ Breakthroughs in semiconductor devices (SiC and GaN)



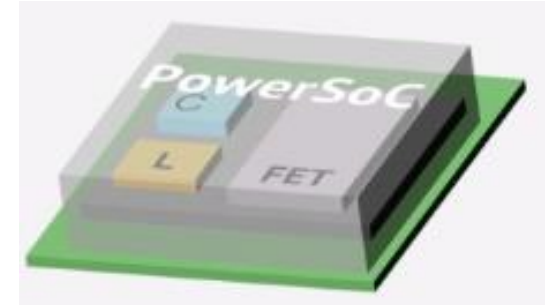
SiC modules



GaN Switches

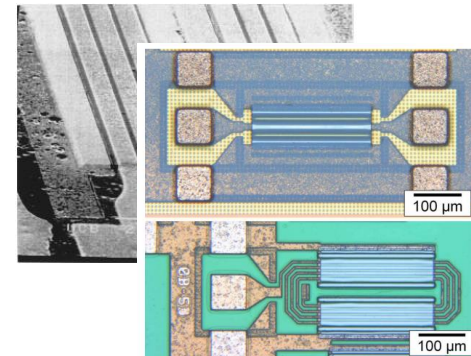
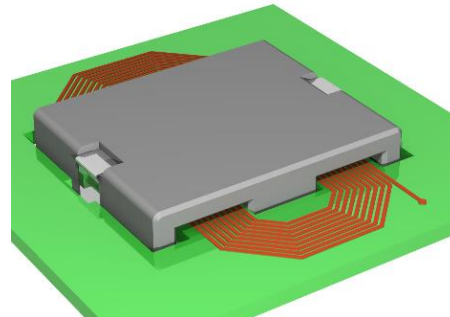
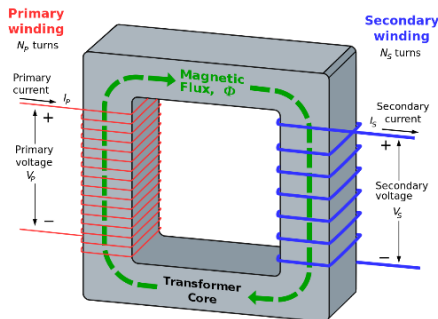


IGBT Modules



Power SoC

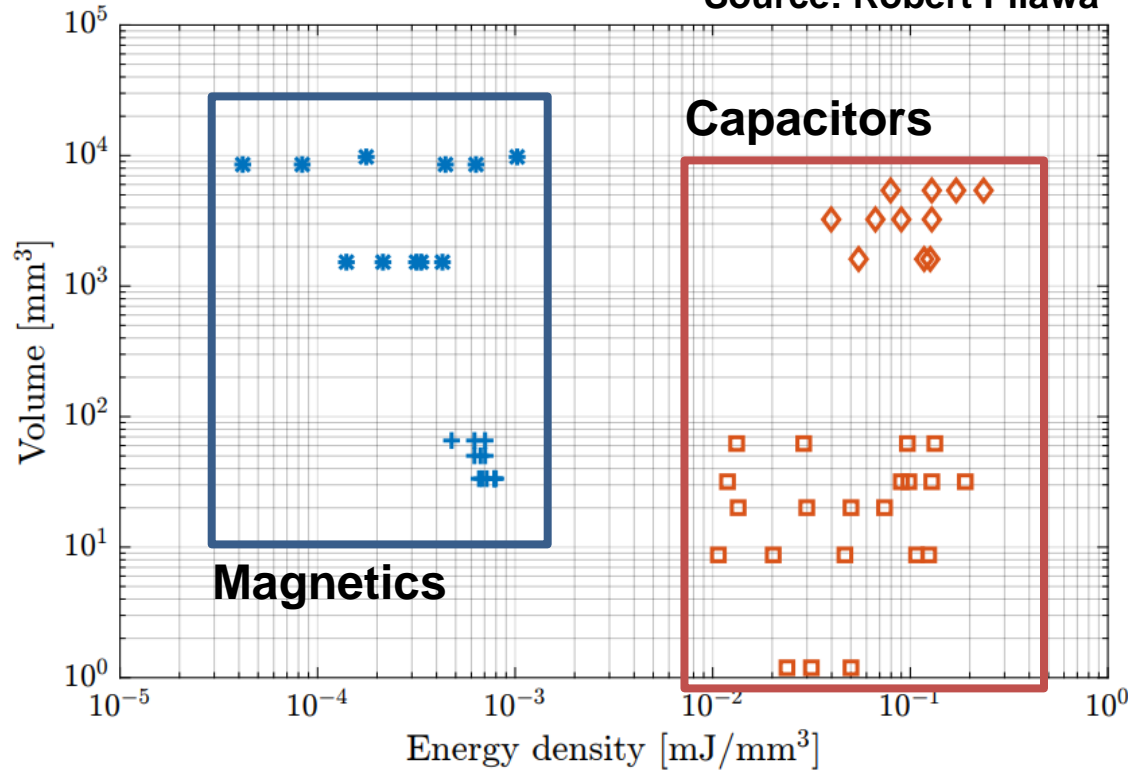
❑ Magnetics are lagging behind



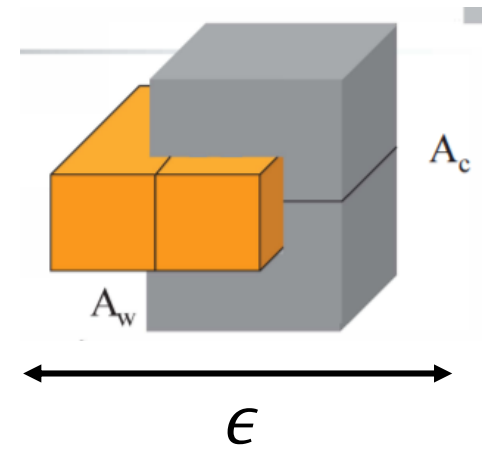
- L. Daniel, "Design of microfabricated inductors", *IEEE Trans. Power Electron.*, 1999
- D.S. Gardner, "Review of on-chip inductor structures with magnetic films", *IEEE Trans. Magn.*, 2009

Energy Density vs. Functionality

Source: Robert Pilawa



Source: Charles Sullivan



$$VA \propto \epsilon^4$$

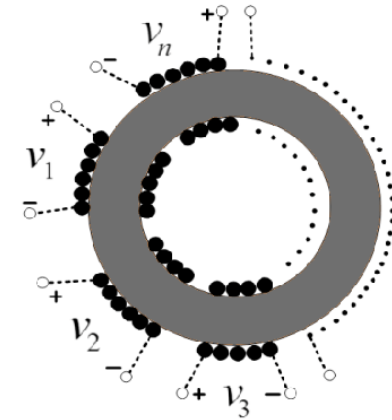
↑
Linear scaling factor

- Capacitors win in energy density
- Larger magnetics has better figure-of-merits
- Magnetics win in functionality
- **Multi-winding, multi-leg, multi-functional magnetics @ high frequency**

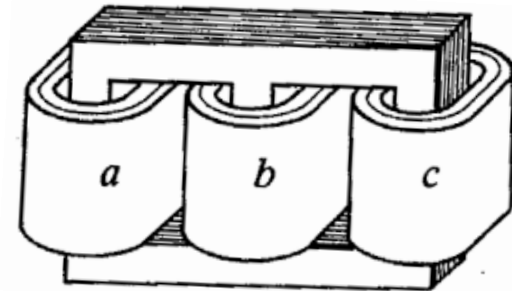
Single Purpose Magnetics



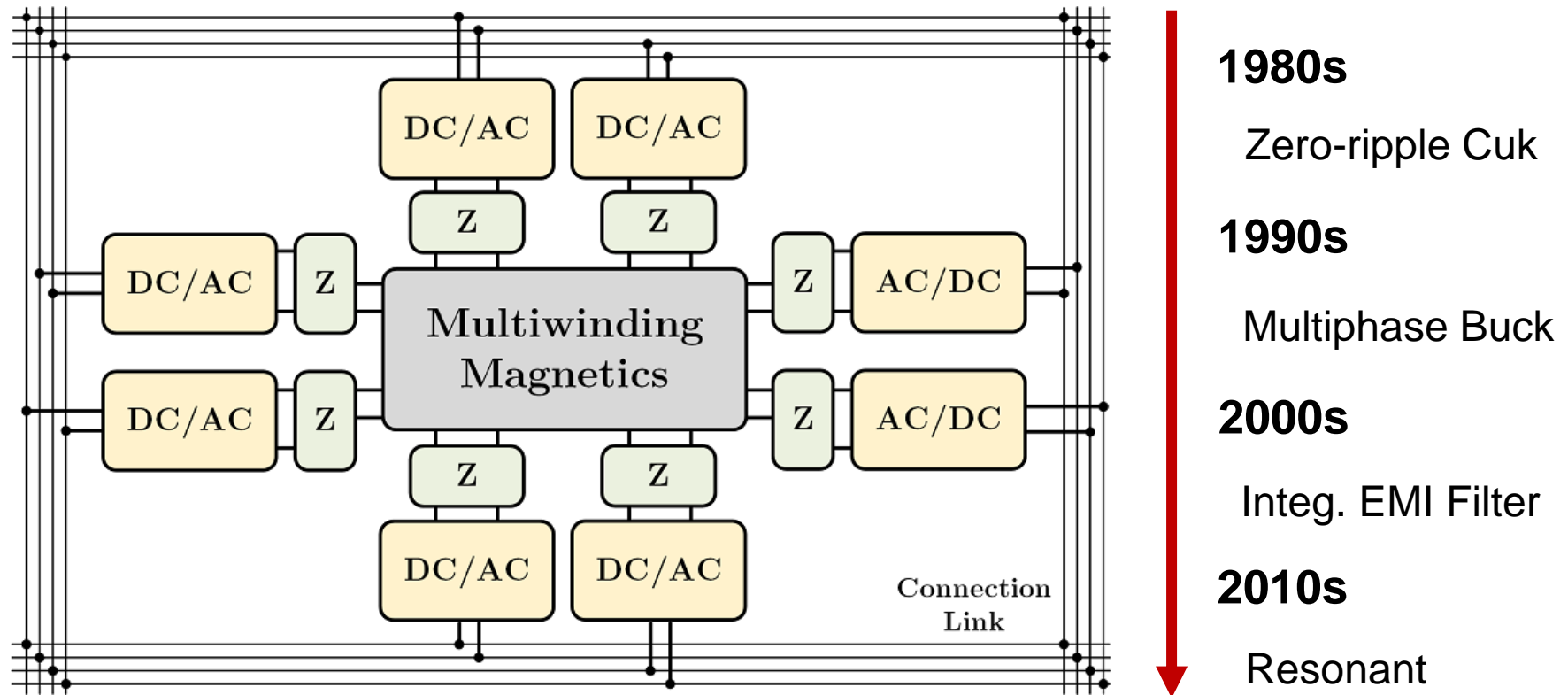
Multiwinding Magnetics



Multileg Magnetics

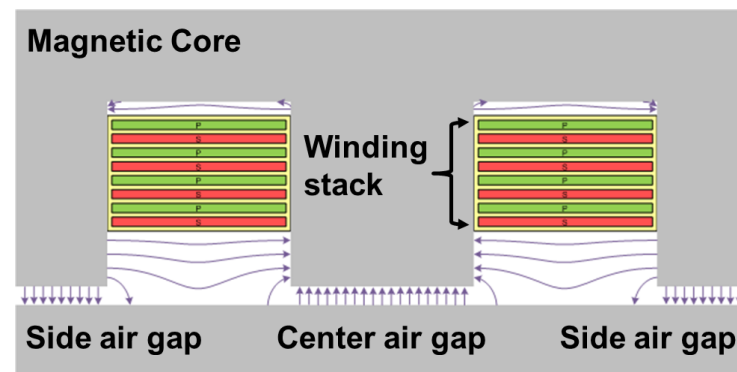
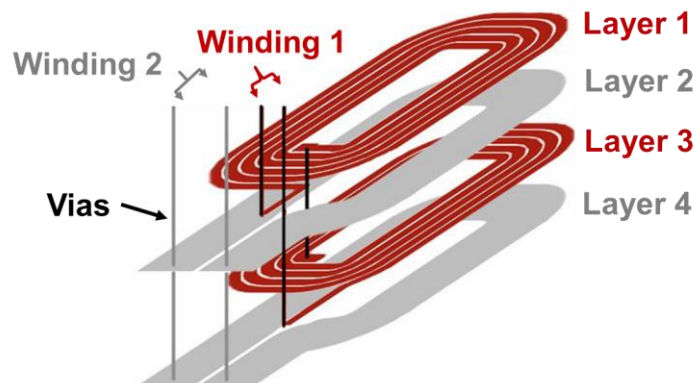


The “integrated magnetics” concept started from 1980s’

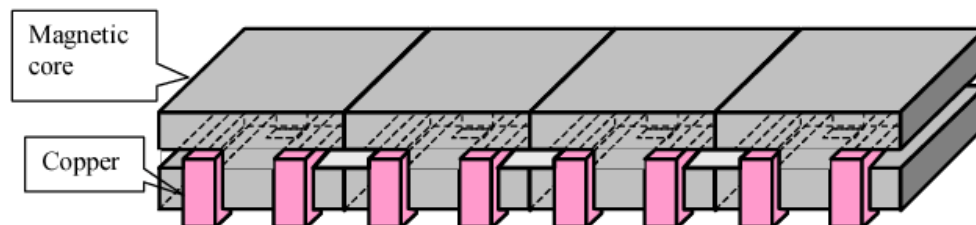
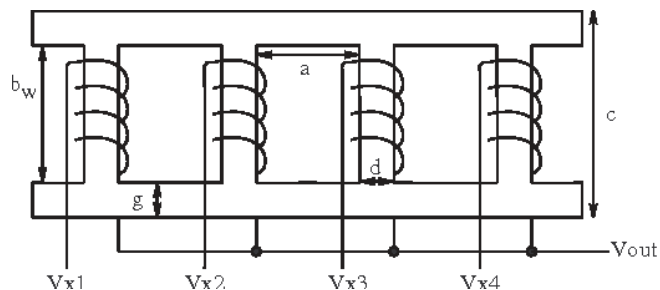


Need tools and methods to design for high frequencies

❑ Multiple windings couple to a single magnetic linkage



❑ Multiple windings couple to multiple magnetic linkages



- M. Chen, "A Systematic Approach to Modeling Impedances and Current Distribution in Planar Magnetics," TPEL 2016
- J. Li et al., "Using coupled inductors to enhance transient performance of multi-phase buck converters," APEC 2004

1. What is the optimal way to interleave many layers?



Alternating interleaved



1 & 3 as primary
2 & 4 as secondary

Symmetric interleaved



1 & 4 as primary
2 & 3 as secondary

More complicated?



.....?

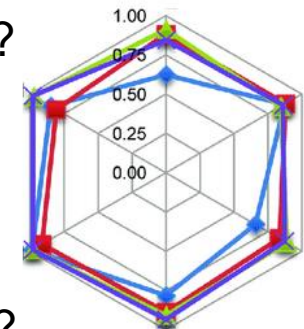
2. What are the optimal winding stack and winding spacing?

Thin Middle Spacing Thick Middle Spacing



3. Multi-object optimization problem

- 1) Interleaving options?
- 2) Materials?
- 3) Geometry?
- 4) Size?
- 5) Efficiency?
- 6) Coupling coefficient?



Every model starts from assumptions ...

(1) MQS assumption

- Assume $\frac{\partial E}{\partial t} = 0$.
- Applicable when the wavelength is much longer than the device size (usually lower than $\sim 100\text{MHz}$).

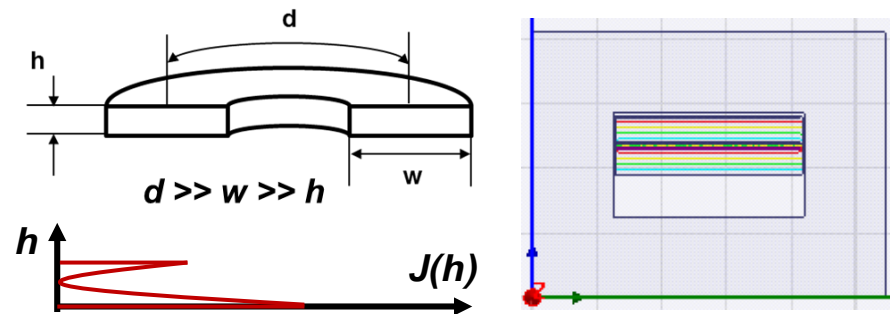
Magneto-Quasi-Static Maxwell's equations

$$\left\{ \begin{array}{l} \nabla E = \frac{\rho}{\epsilon_0} \\ \nabla B = 0 \\ \nabla \times E = -\frac{\partial B}{\partial t} \\ \nabla \times B = \mu_0 \left(J + \epsilon_0 \frac{\partial E}{\partial t} \right) \end{array} \right. \quad \text{Ignore the time evolution of the electric field}$$

(2) 1-D assumption

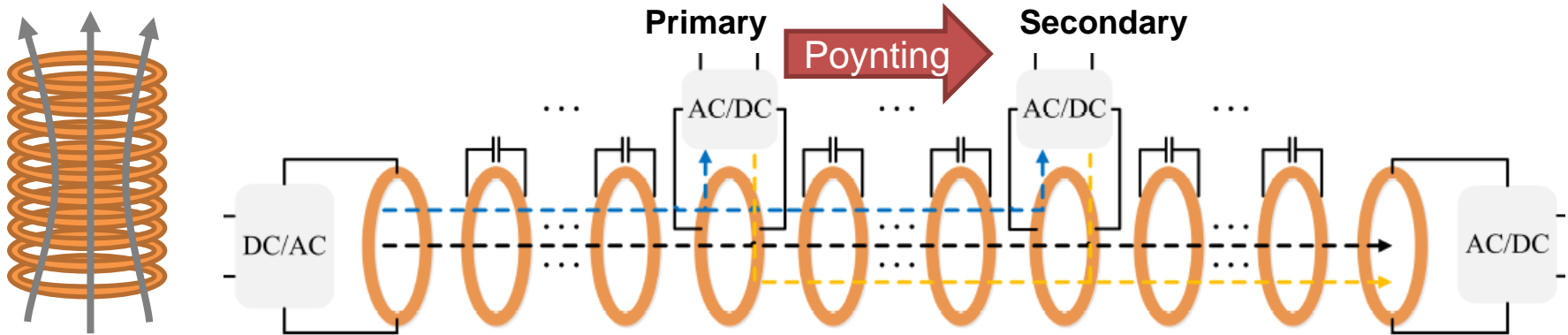
- Fields vary only along the thickness direction.
- Applicable when the flux is guided by the magnetic core.

Magnetic core guides the flux

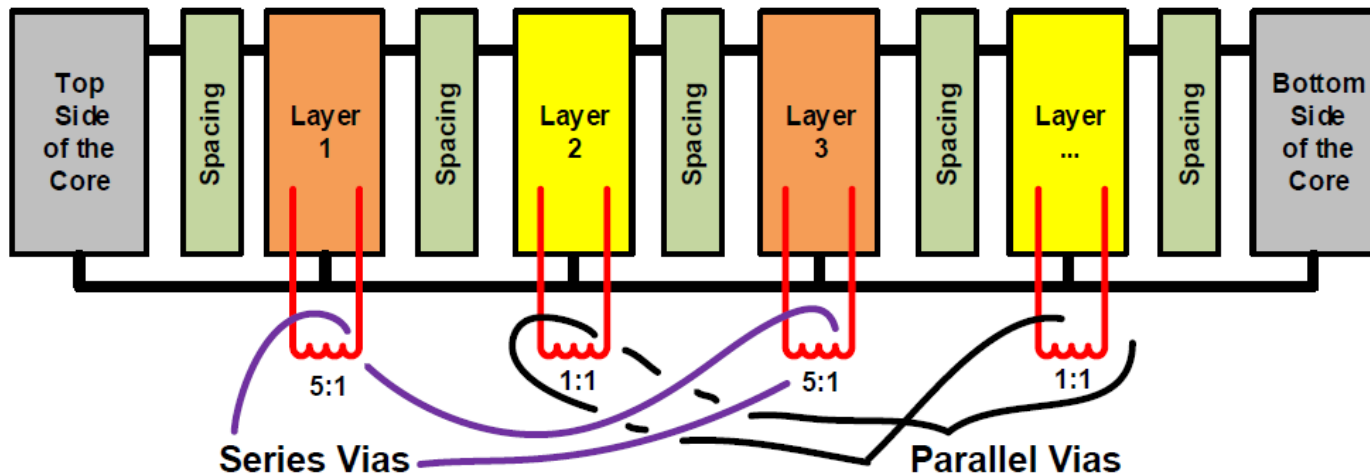


Skin and proximity effects change current distribution

□ 1-D energy wave (Poynting vector) propagation principles



□ Modular lumped circuit models for repeating building blocks



Field diffusion equations:

$$H_X(z) = \frac{H_T \sinh(\Psi z) + H_B \sinh(\Psi(h - z))}{\sinh(\Psi h)}$$

Ampere's law:

$$\nabla \times H = J = \sigma E \quad \Psi = \frac{1+j}{\delta} \quad \delta = \sqrt{\frac{2}{\mu\omega\sigma}}$$

E field as a function of H and K:

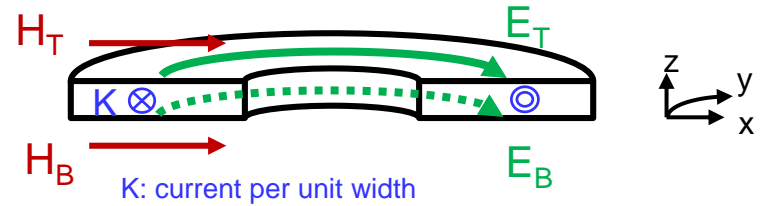
$$\begin{cases} E_T = E_Y(h) = \frac{\Psi}{\sigma} \left(\frac{H_T e^{\Psi h} - H_B}{e^{\Psi h} - e^{-\Psi h}} - \frac{H_B - H_T e^{-\Psi h}}{e^{\Psi h} - e^{-\Psi h}} \right) & Z_a = \frac{\Psi(1 - e^{-\Psi h})}{\sigma(1 + e^{-\Psi h})} \\ E_B = E_Y(0) = \frac{\Psi}{\sigma} \left(\frac{H_T - H_B e^{-\Psi h}}{e^{\Psi h} - e^{-\Psi h}} - \frac{H_B e^{\Psi h} - H_T}{e^{\Psi h} - e^{-\Psi h}} \right) & Z_b = \frac{2\Psi e^{-\Psi h}}{\sigma(1 - e^{-2\Psi h})} \end{cases}$$

KVL/KCL relationships:

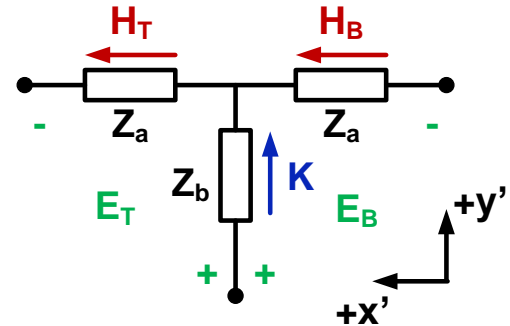
V/m Ω A/m

$$\begin{cases} E_T = Z_a H_T + Z_b K & \text{KVL} \\ E_B = Z_b K - Z_a H_B & \text{KVL} \\ K = H_T - H_B & \text{KCL} \end{cases}$$

Electromagnetic Fields



Modular Layer Model



H & K : through variables ~ unit (A/m)
 E : across variable ~ unit (V/m)
 Z_a, Z_b : impedances ~ unit (Ω)

Intuition:

- Two three-terminal networks
- Connected by the H field between them

Faraday's Law and Field Continuity

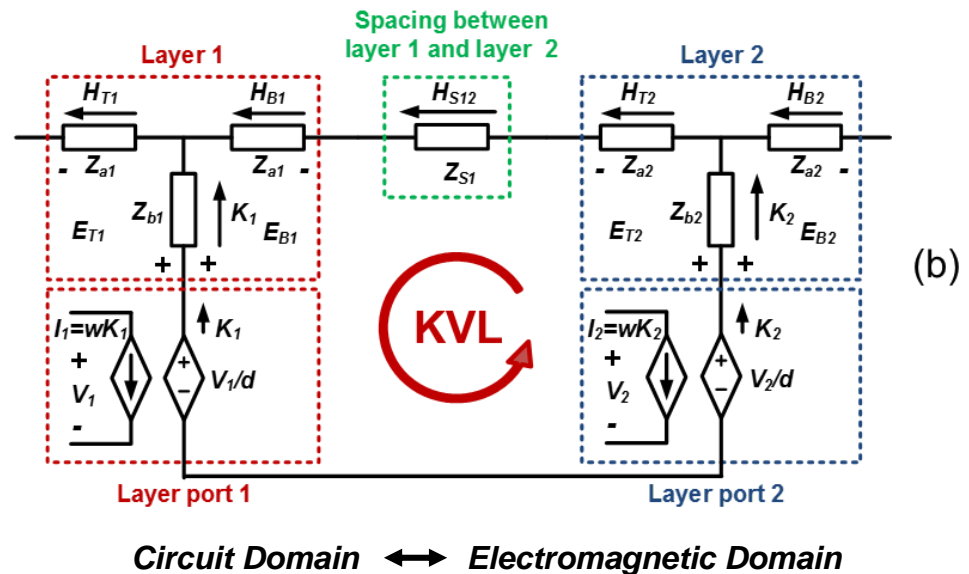
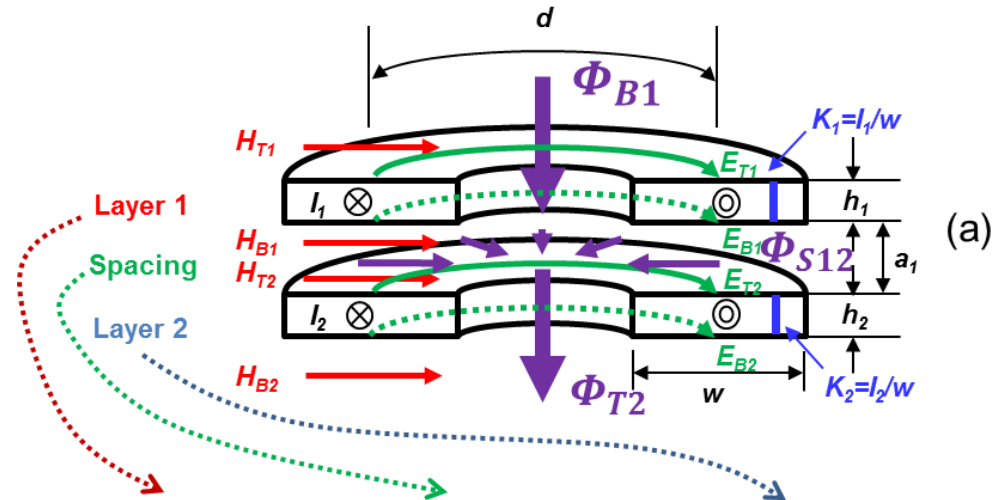
$$E_{B1}d - V_1 = -\frac{d\Phi_{B1}}{dt} \quad E_{T2}d - V_2 = -\frac{d\Phi_{T2}}{dt}$$

$$\frac{d\Phi_{T2}}{dt} = \frac{d\Phi_{B1}}{dt} + \frac{d\Phi_A}{dt}$$

Flux Linking Two Layers:

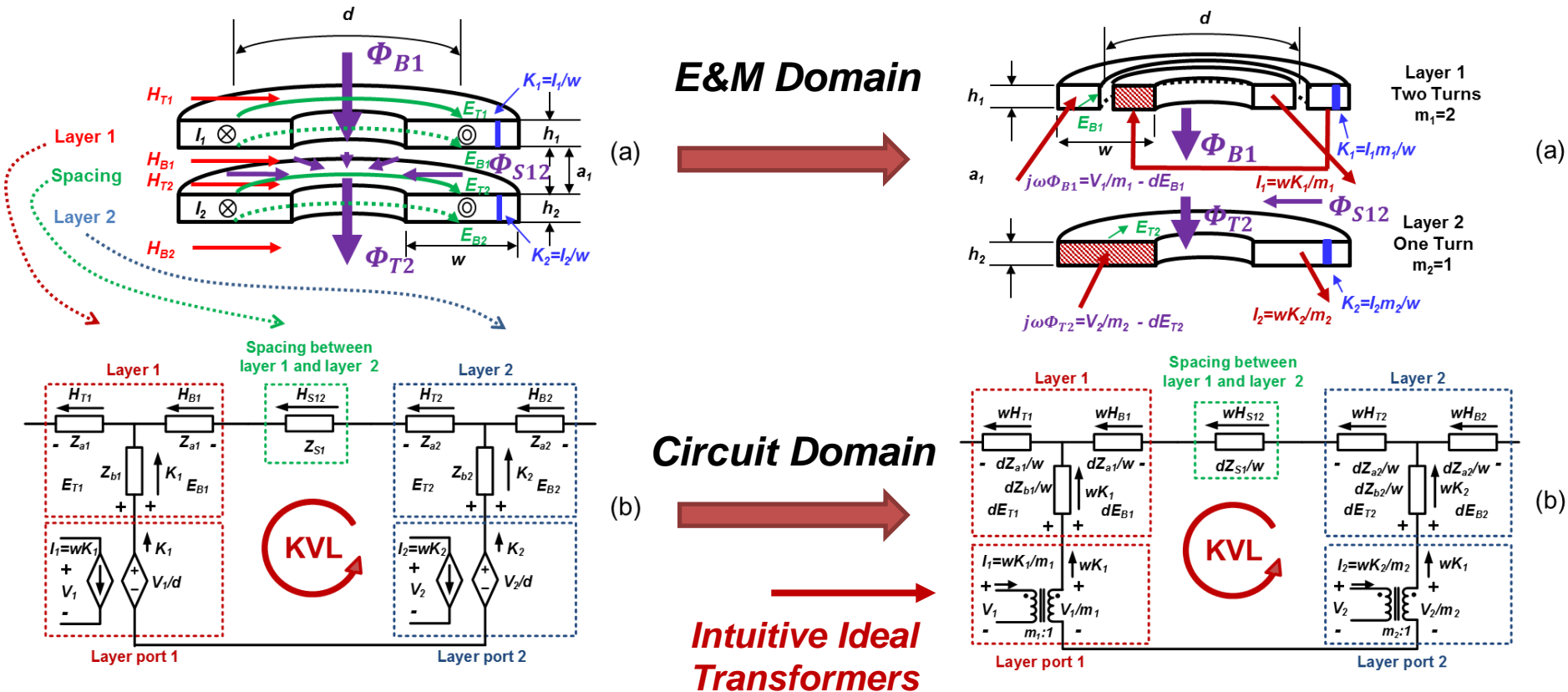
An additional KVL equation

$$\underbrace{j\omega\mu_0 a_1}_{\Omega} \underbrace{H_{S12}}_{A/m} = \underbrace{\frac{V_2}{d} - E_{T2} - \frac{V_1}{d} + E_{B1}}_{V/m}$$



Fields distributions in multiple-turns layers are linearly related to those in single-turn layers

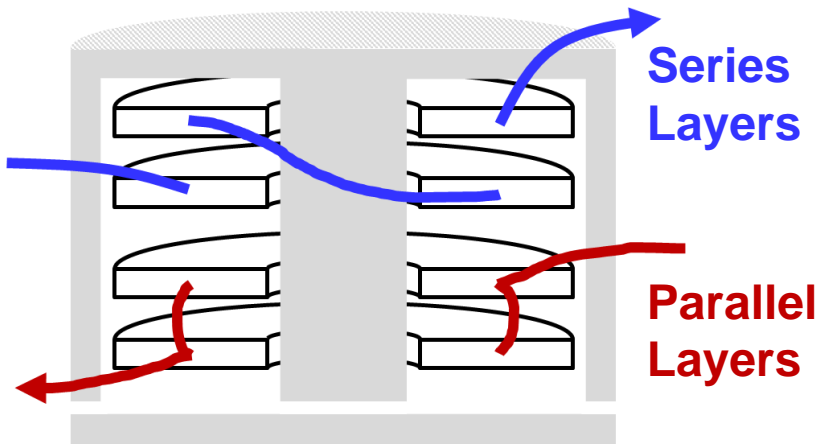
Multiple turns \rightarrow Additional Linear Conversions



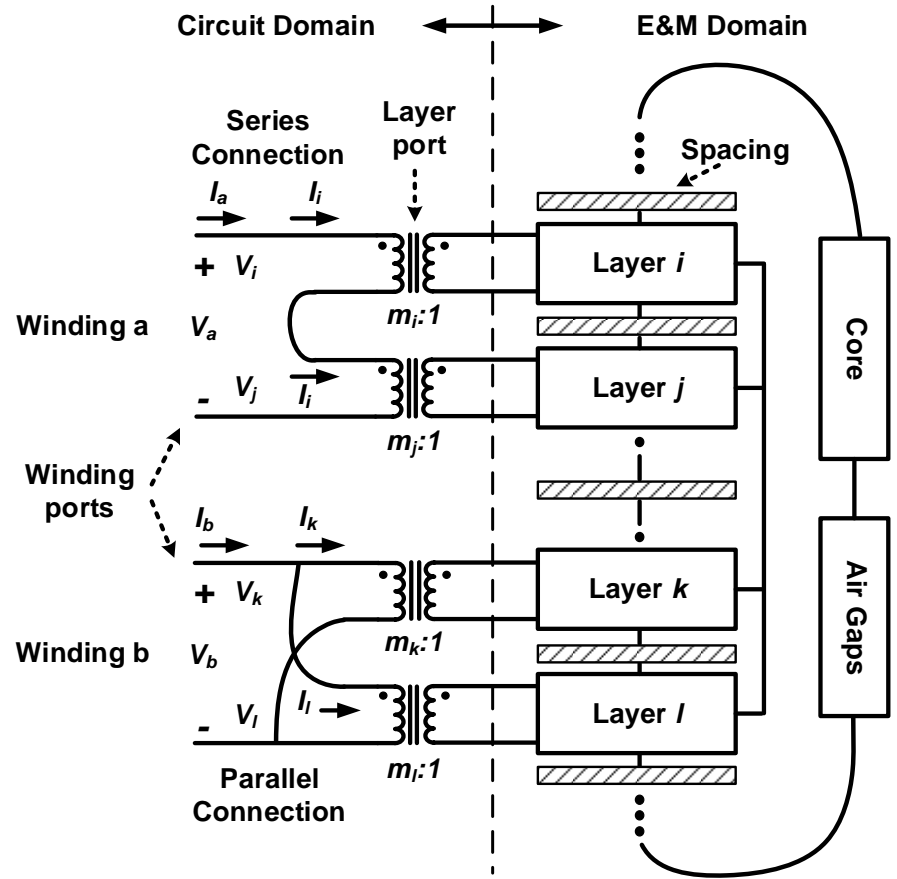
Modeling vias is equivalent to adding KVL, KCL constraints:

Layer i and Layer j in series
 Layer k and Layer l in parallel

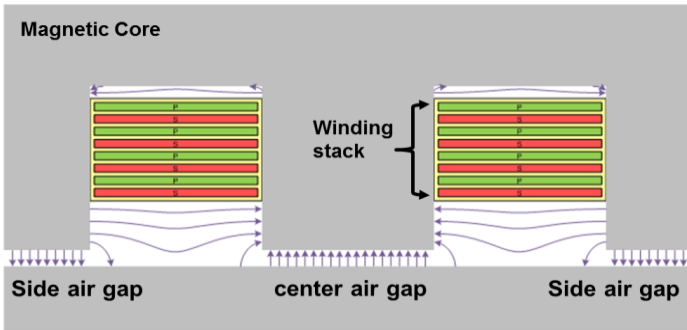
$$\begin{cases} V_i + V_j = V_a \\ V_k = V_l = V_b \end{cases} \quad \begin{cases} I_i = I_j = I_a \\ I_k + I_l = I_b \end{cases}$$



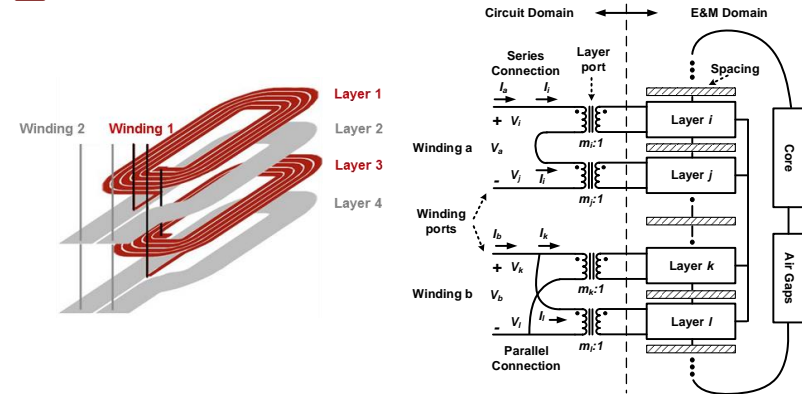
Connect the layer ports in the same pattern as they are in the real circuit



1 Geometry Information

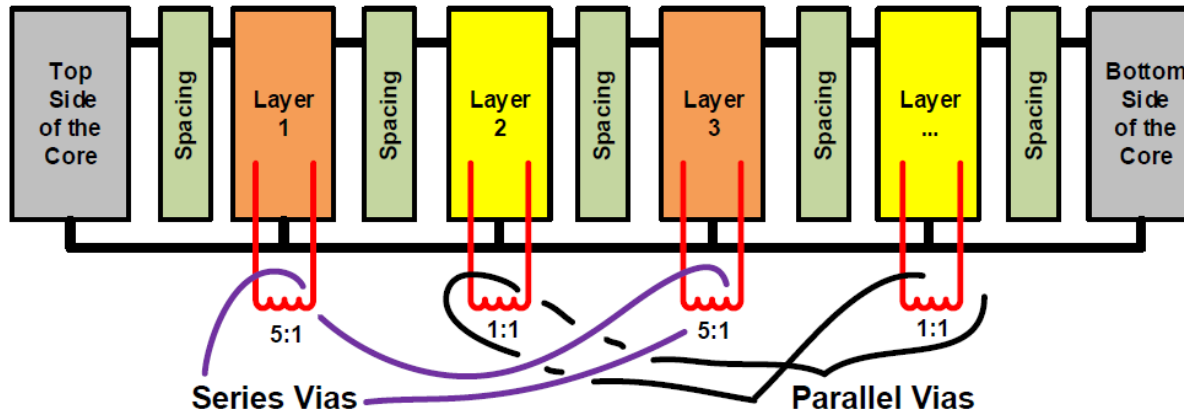


3 SPICE Netlist



2

Modular Layer Model

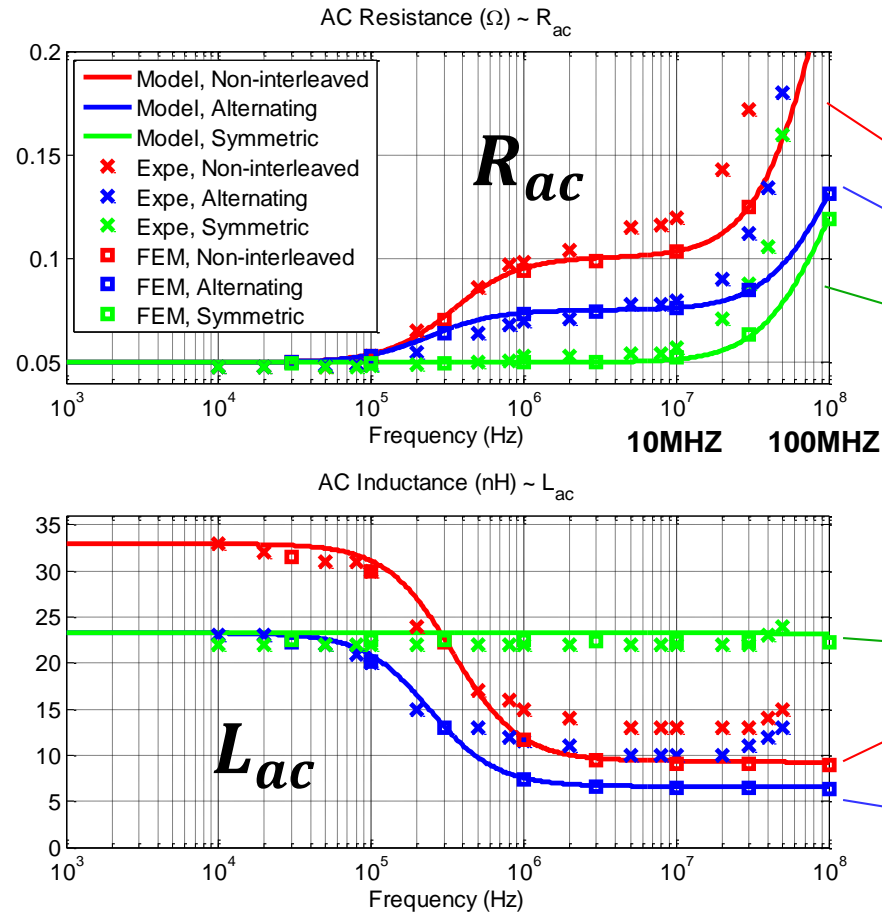
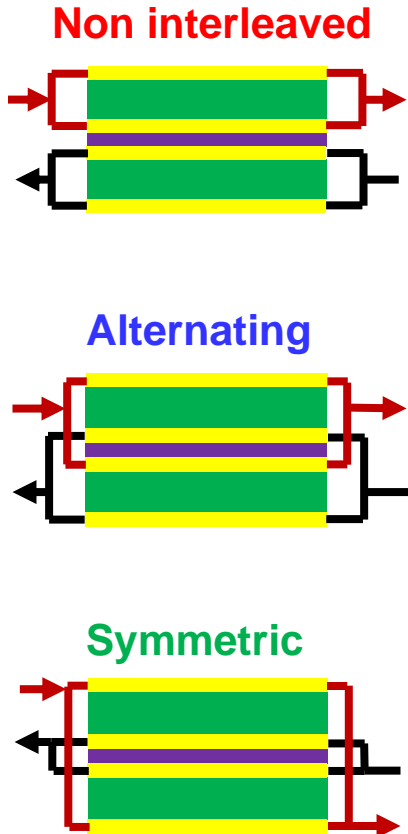


Simulations!



Search: M2SPICE

Comparing the P_{ac} and E_{ac} of three 1:1 transformers with three different interleaving patterns



$$P_{ac} = \sum I^2 R_{ac}$$

Non Interleaved

Alternating

Symmetric

$$E_{ac} = \frac{1}{2} \sum I^2 L_{ac}$$

Symmetric

Non interleaved

Alternating

Interleaving has to be done in the right way !!!

Multi-Input Multi-Output Power Electronics Systems



Battery Banks



Server Racks



Solar Farms



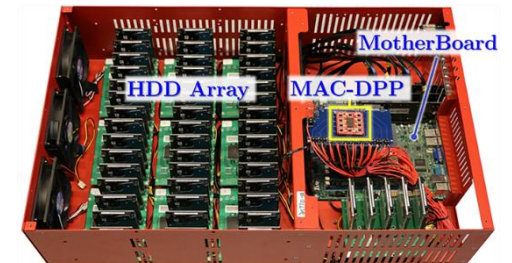
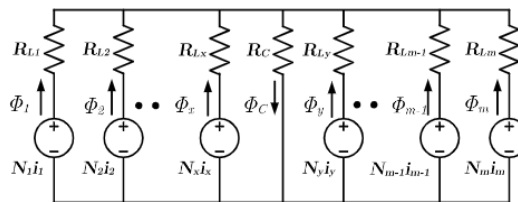
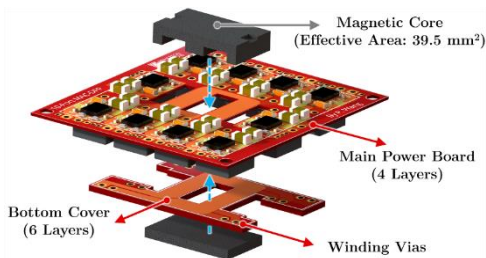
Magnetics Design



Circuit Topology

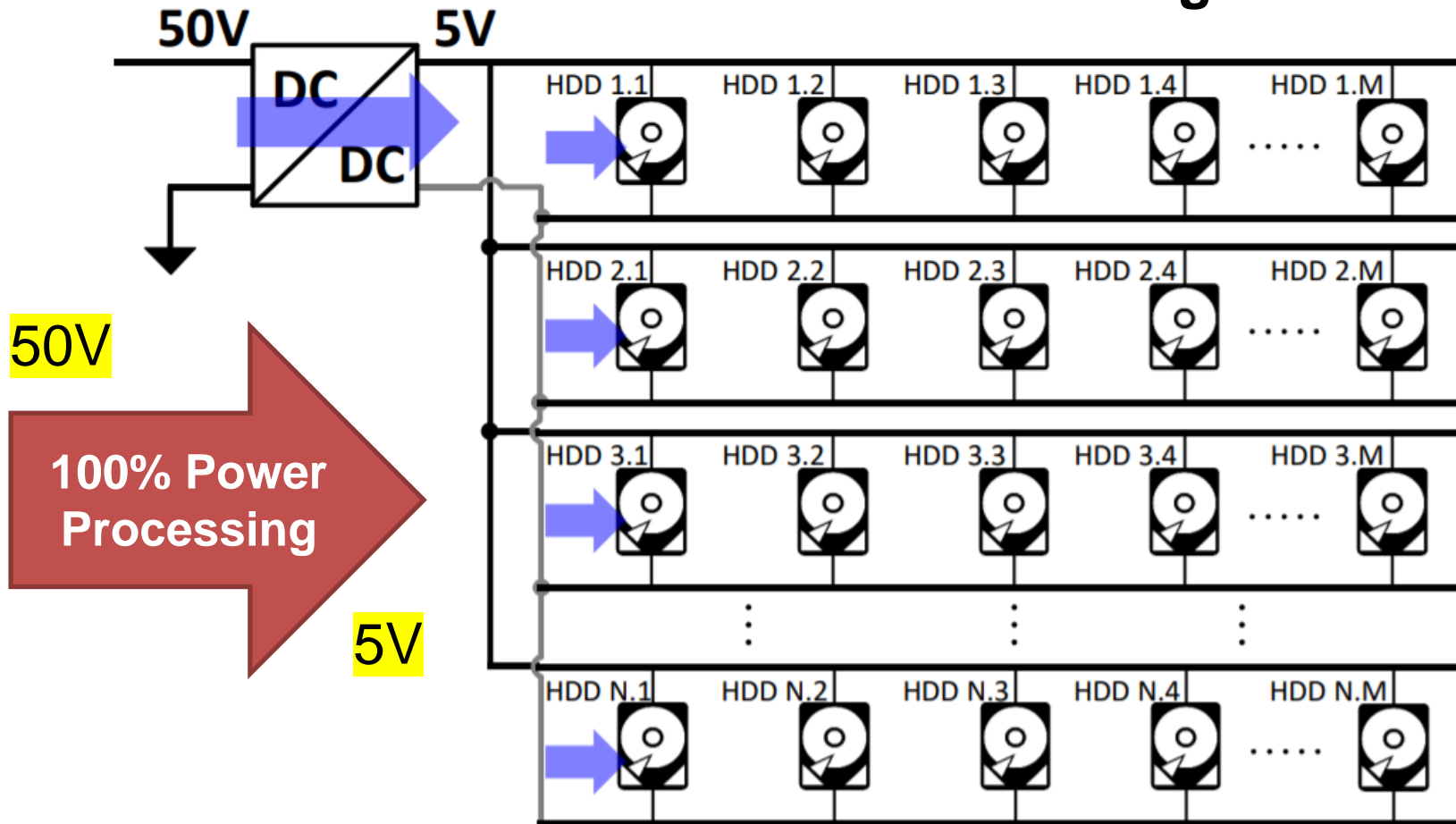


System Integration

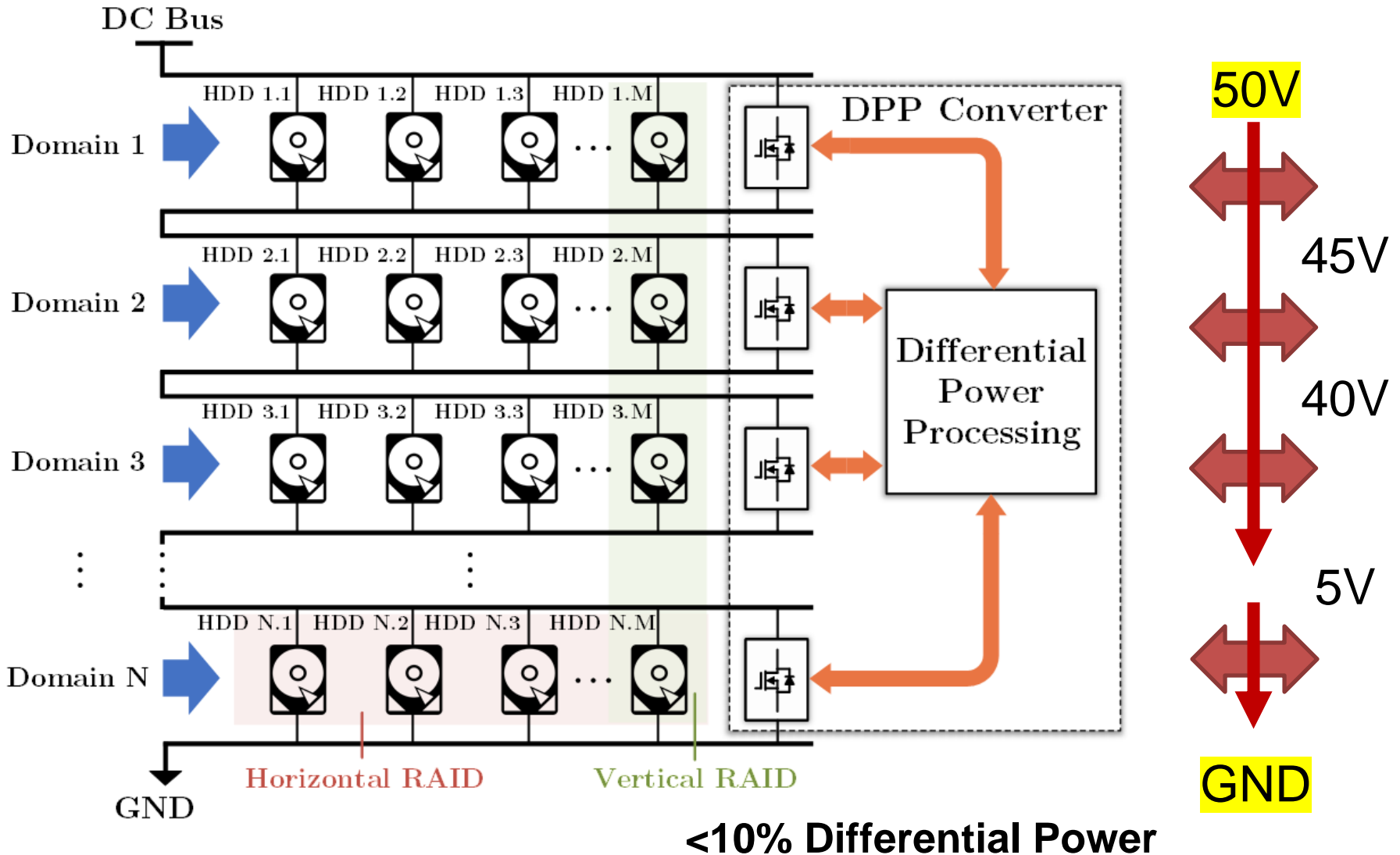


A Conventional Dc-Dc Approach

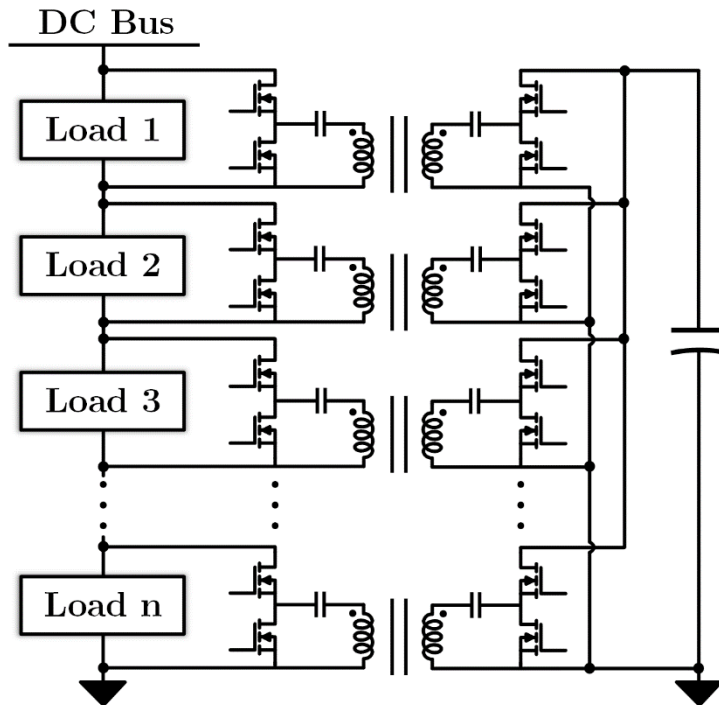
Hard Drive Data Storage Server



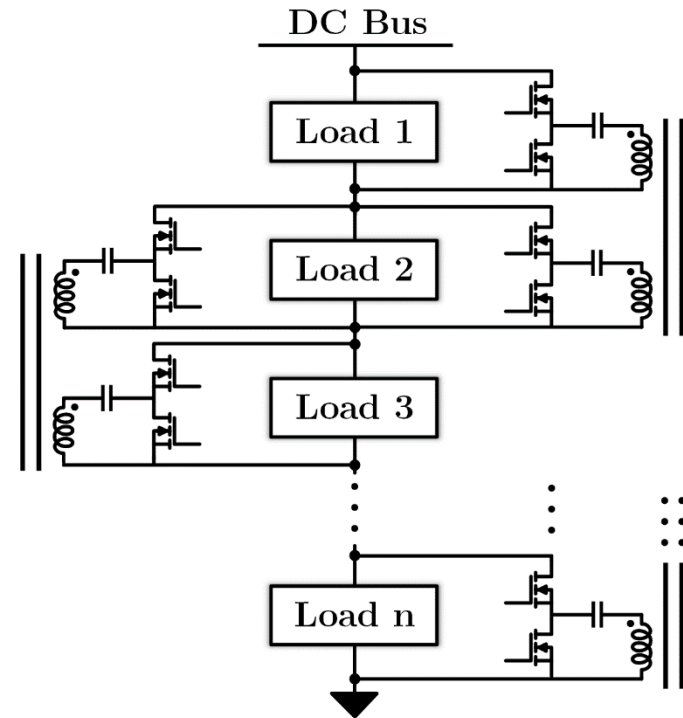
Differential Power Processing



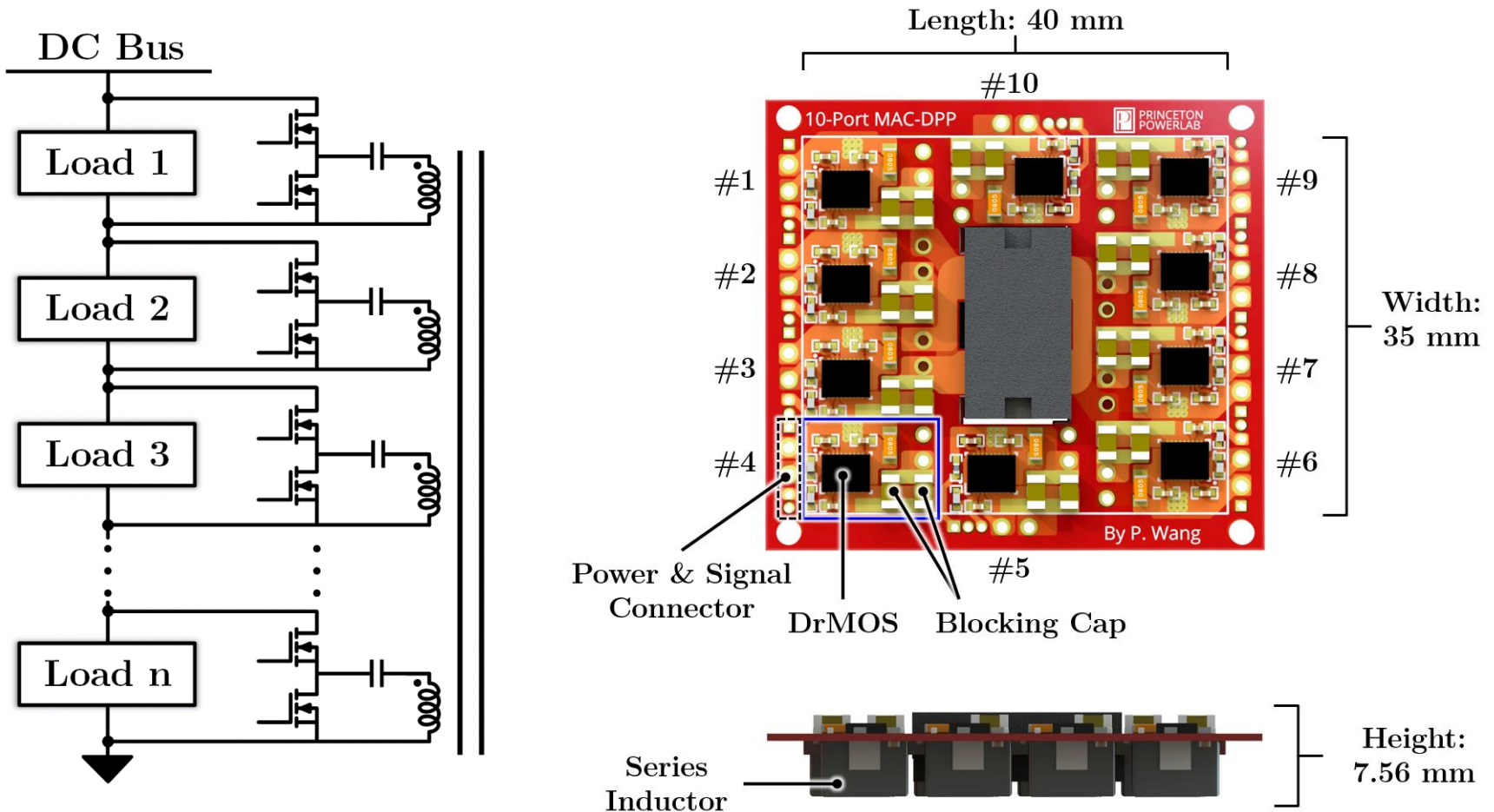
DPP with a buffer port



Ladder DPP

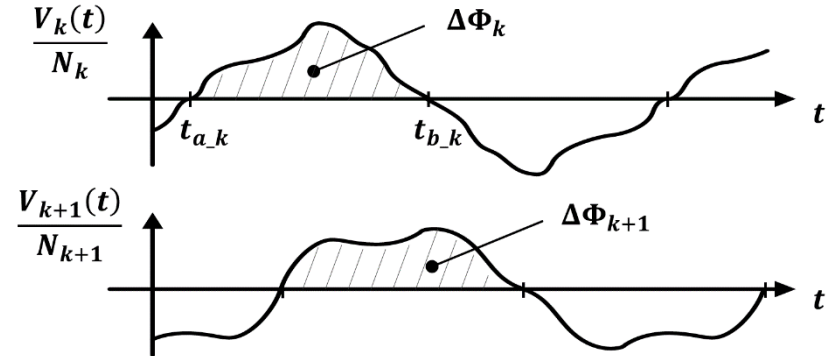
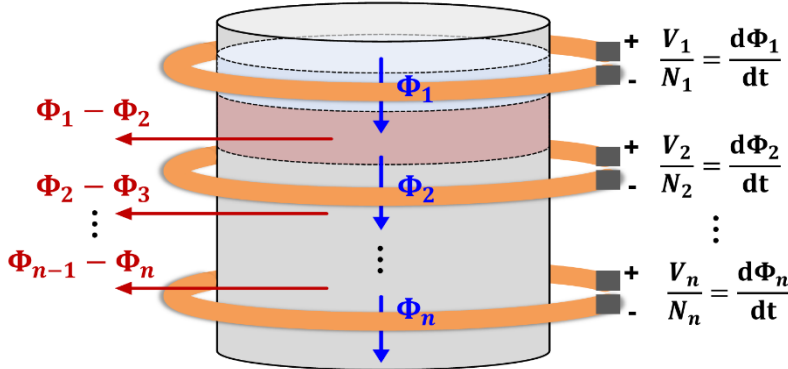


- E. Candan, P. S. Shenoy and R. C. N. Pilawa-Podgurski, "A Series-Stacked Power Delivery Architecture with Isolated Differential Power Conversion for Data Centers," TPEL 2016.
- H. Schmidt and C. Siedle, "The charge equalizer-a new system to extend battery lifetime in photovoltaic systems, UPS and electric vehicles," INTELEC 1993.

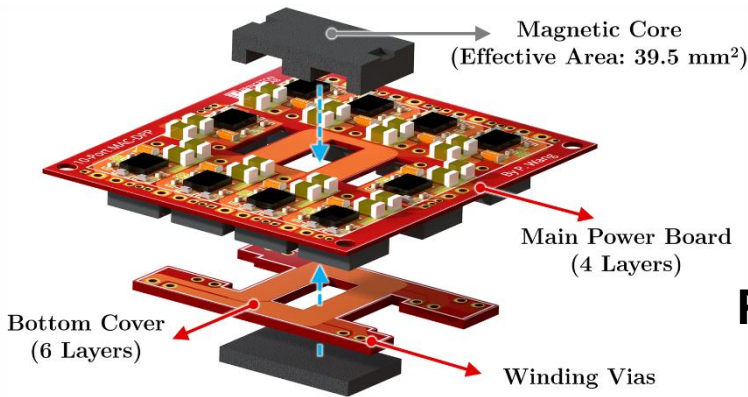


- P. Wang, M. Chen et al., "A 99.7% Efficient 300 W Hard Disk Drive Storage Server with Multiport Ac-Coupled Differential Power Processing (MAC-DPP) Architecture," ECCE 2019

Transformer saturation requirements: maximum volt-seconds per turn

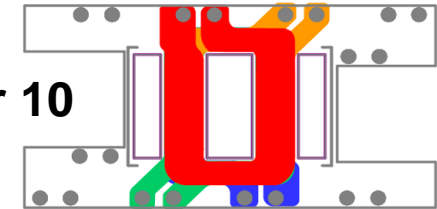


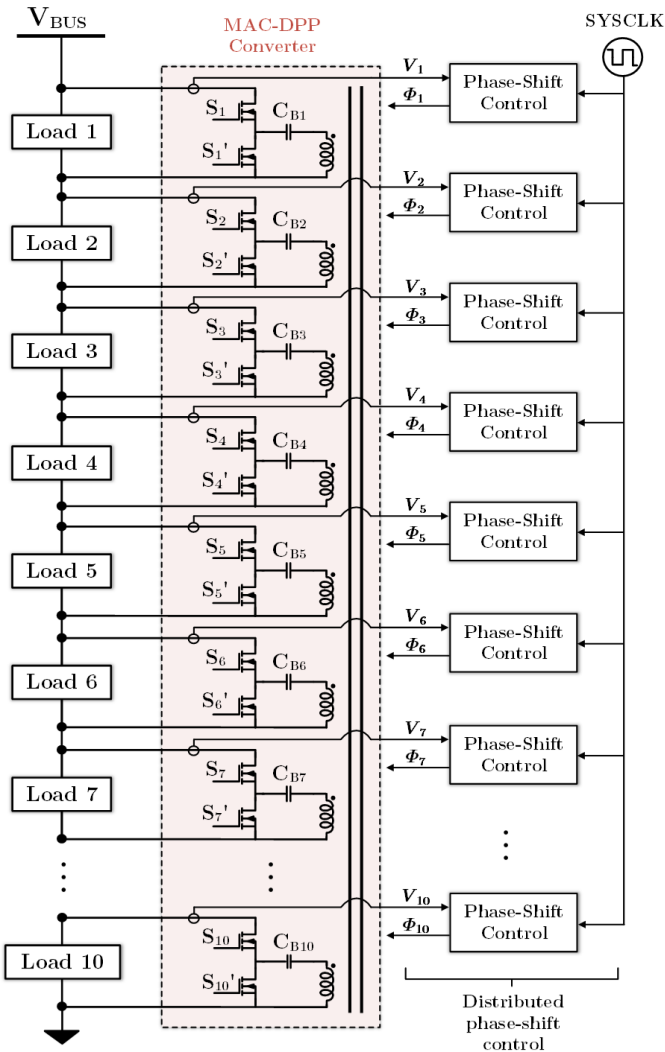
3D stacked multiwinding transformer with modular planar modeling



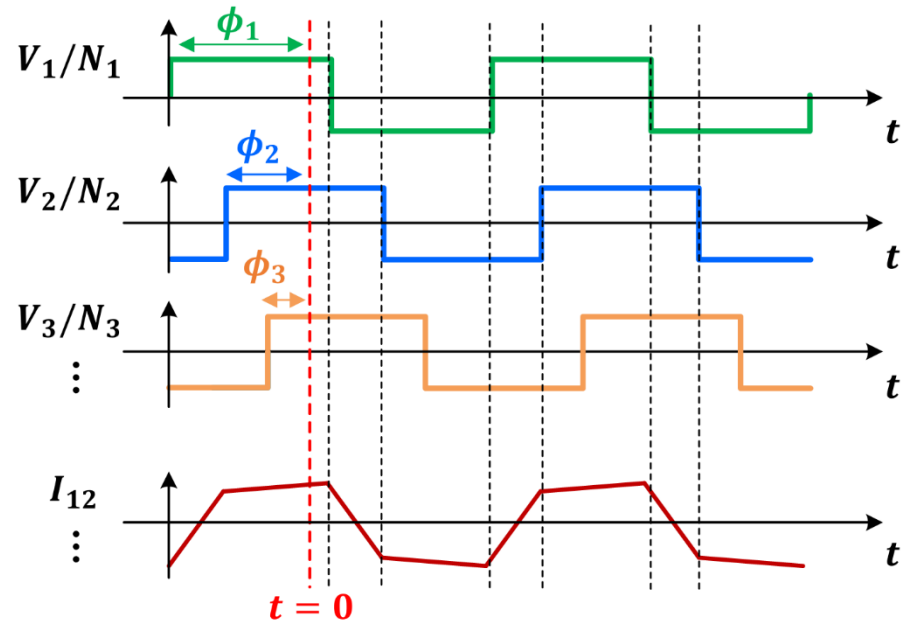
PCB1: Layer 1 – Layer 6

PCB2: Layer 7 – Layer 10

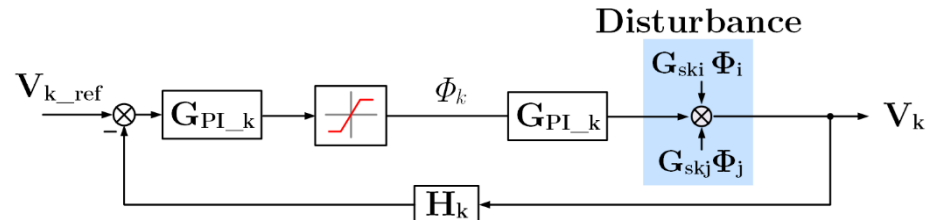




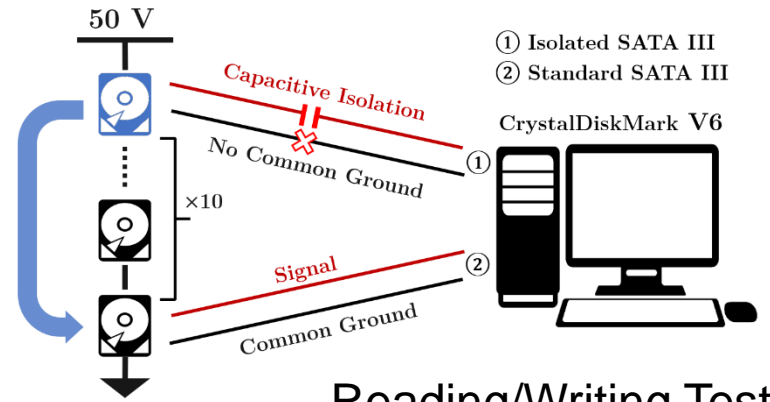
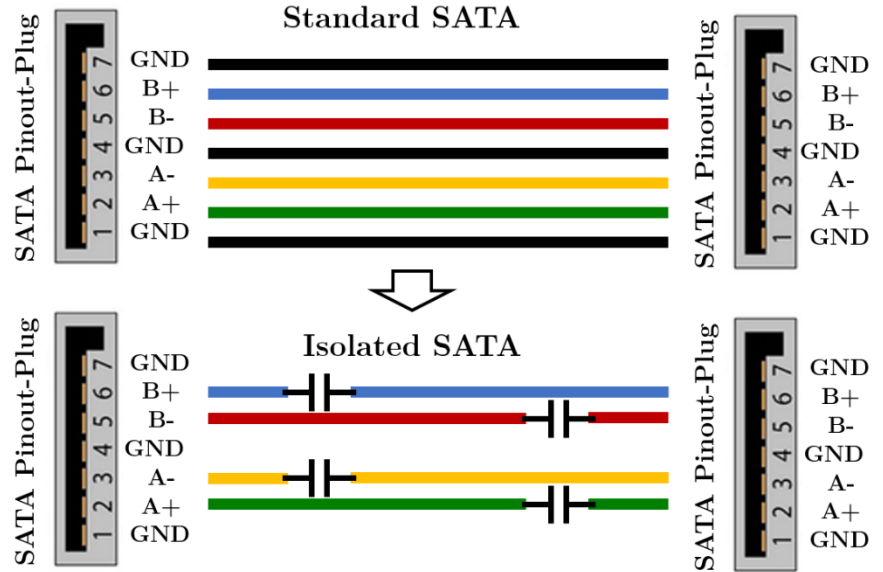
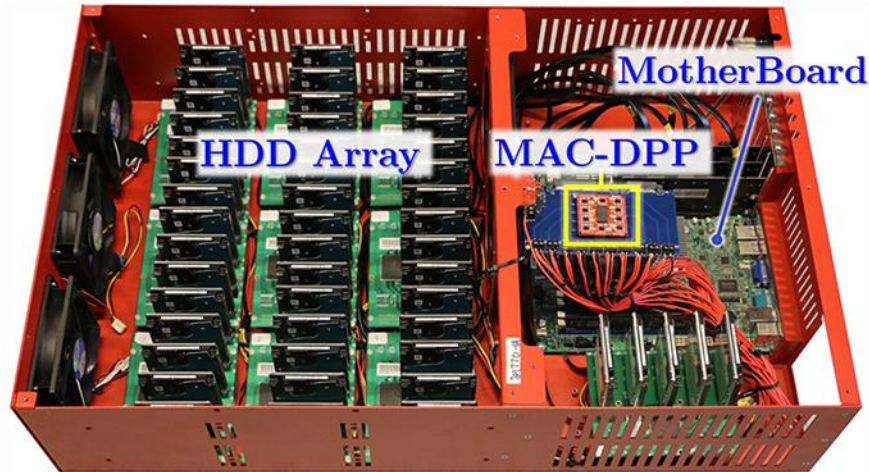
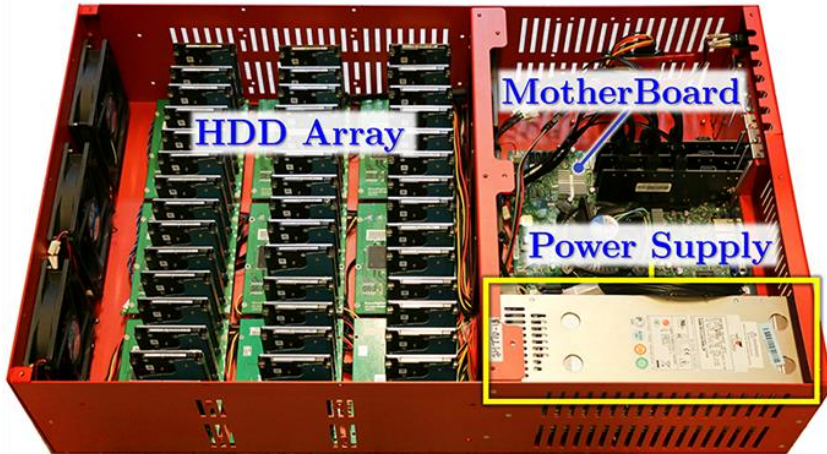
Phase shift determines the power flow



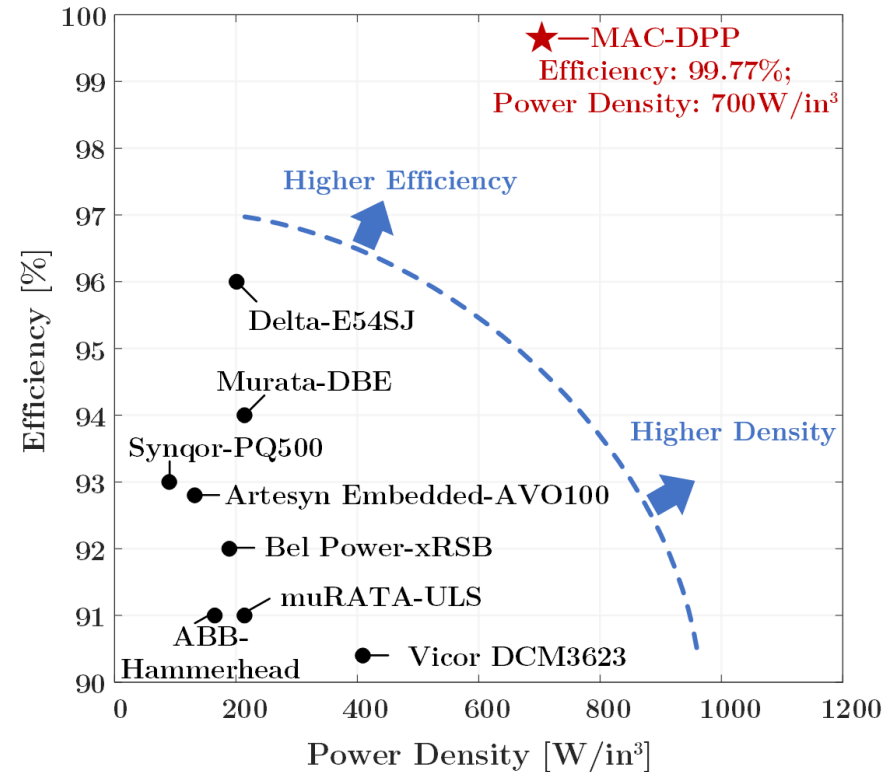
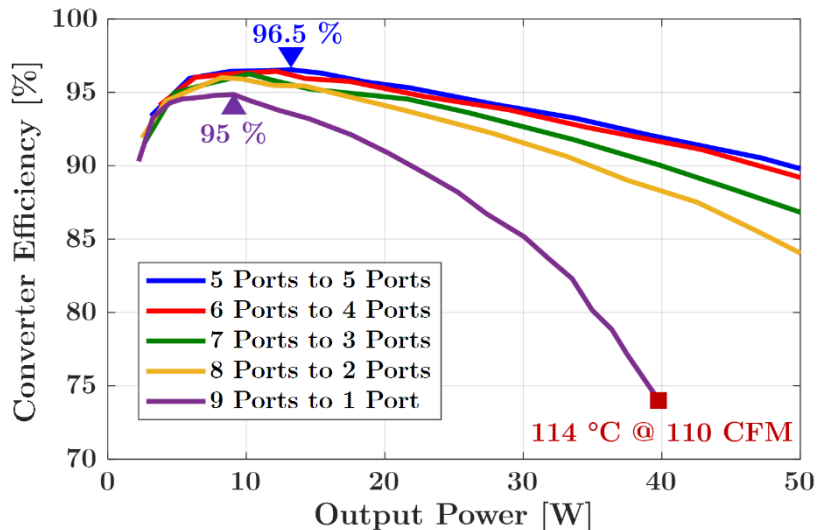
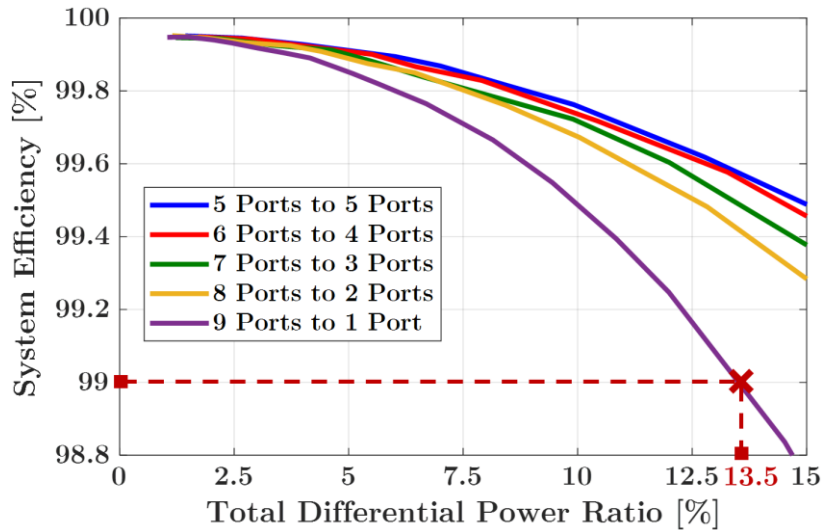
Block diagram of the distributed control



Complete HDD Storage System



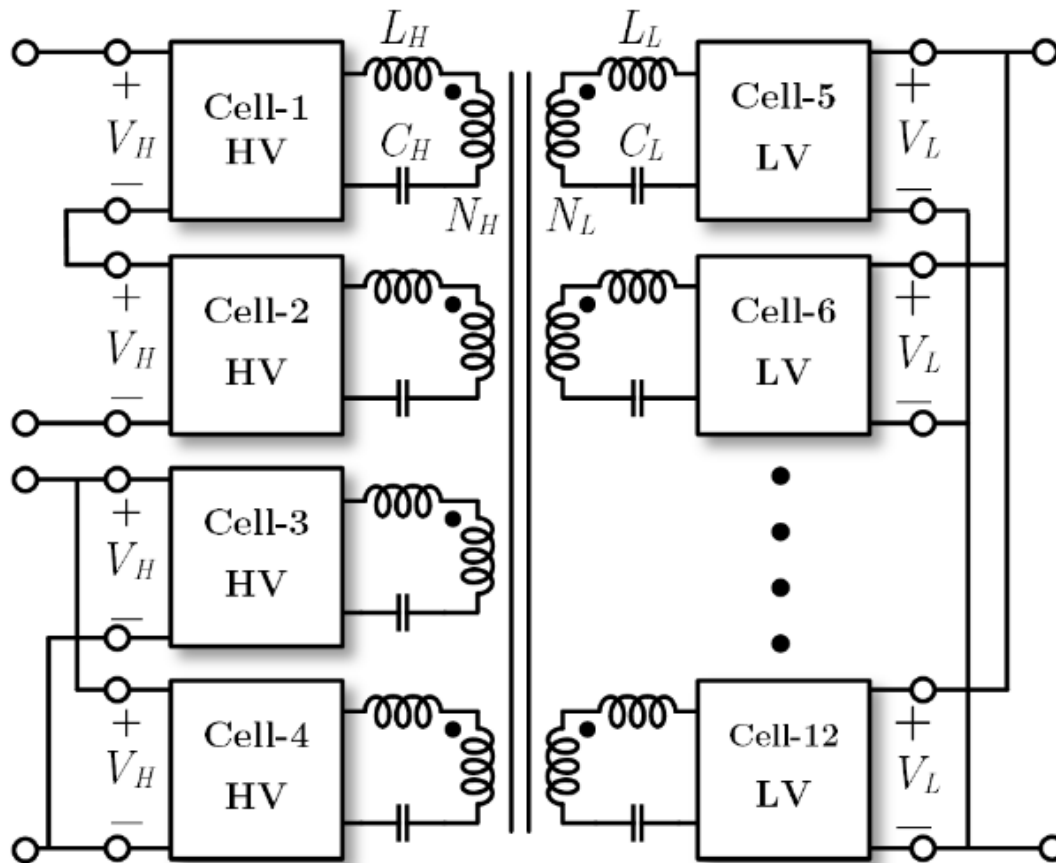
Performance of the DPP Architecture



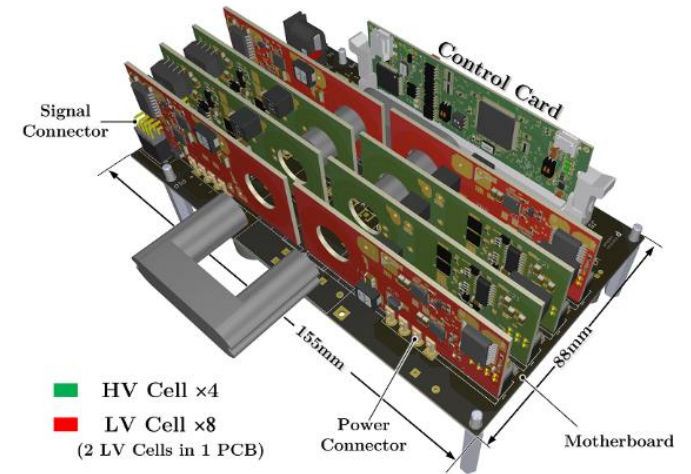
Summary:

- Multiwinding transformer enables ultra high performance DPP
- DPP architecture fits well to large scale modular systems

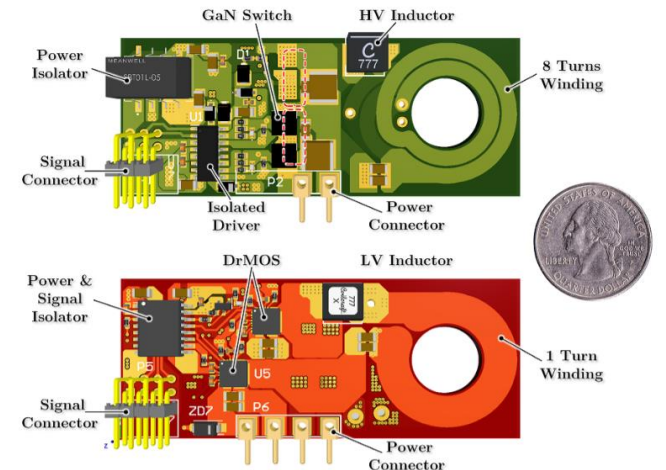
MIMO Reconfigurable Energy Router



Series-Parallel Reconfigurable

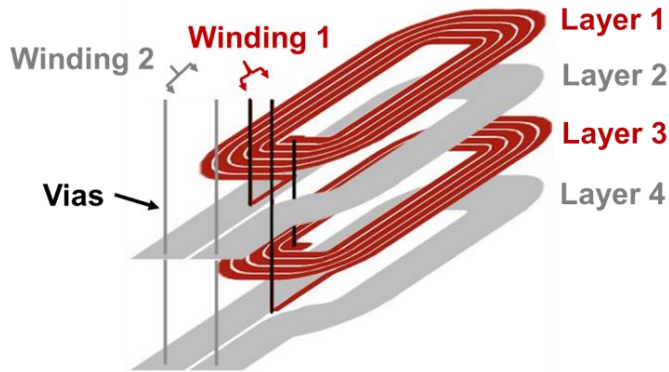


- HV Cell x4
- LV Cell x8
(2 LV Cells in 1 PCB)

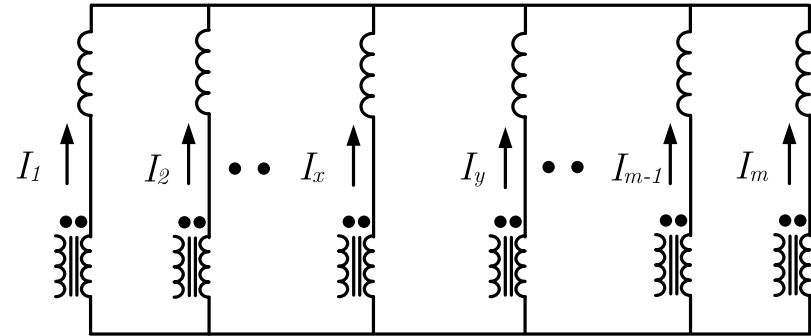


- Y. Chen, M. Chen et al., "LEGO-MIMO Architecture: A Universal Multi-Input Multi-Output (MIMO) Power Converter with Linear Extendable Group Operated (LEGO) Power Bricks," ECCE19.

- Multiple winding coupled to a single flux linkage



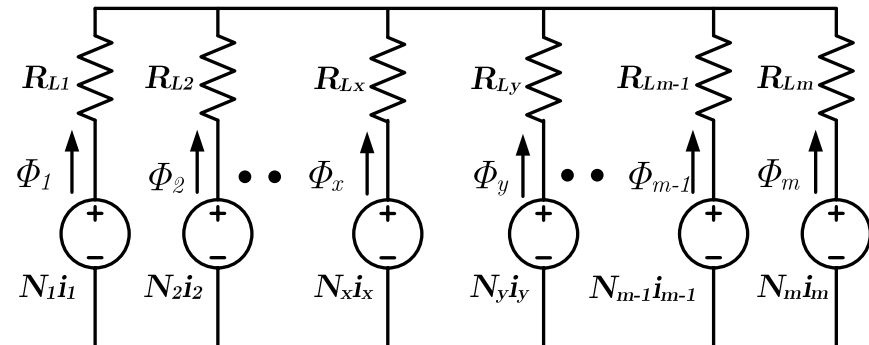
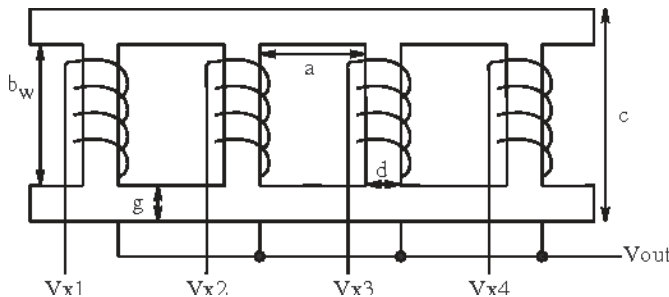
electrical circuit model



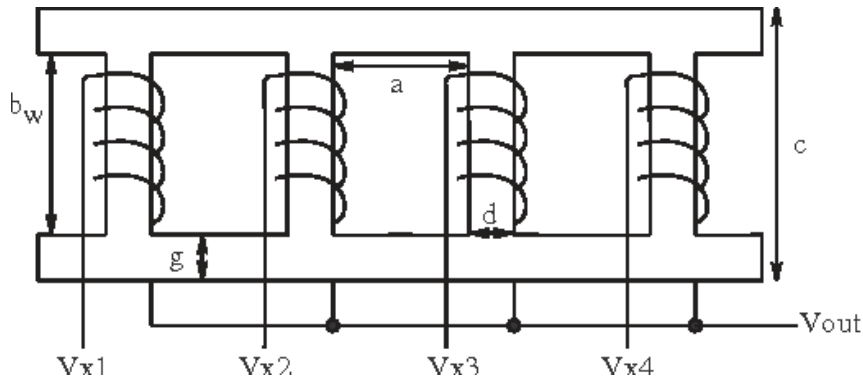
- Multiple windings coupled to multiple flux linkages



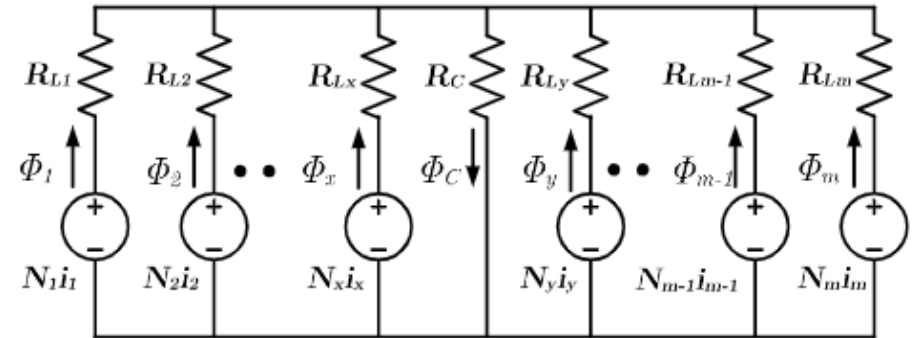
reluctance circuit model



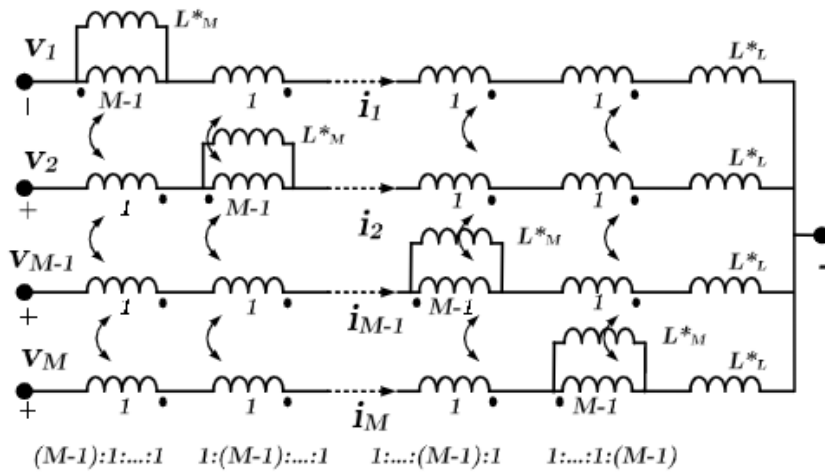
Physical Structure



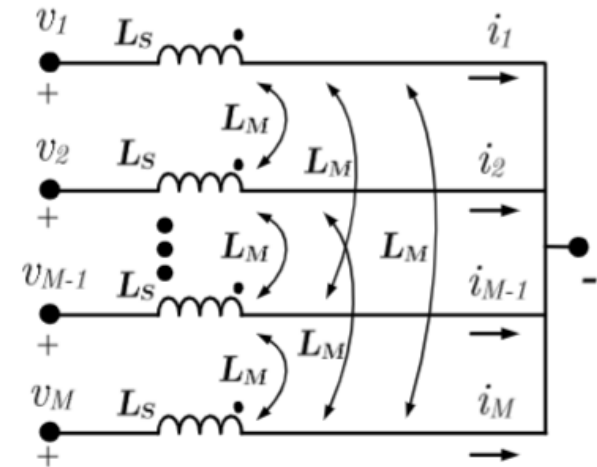
Reluctance Model



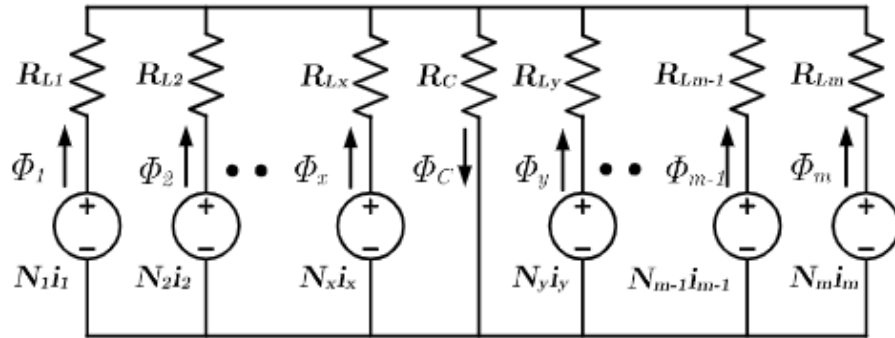
Multiwinding Transformer Model



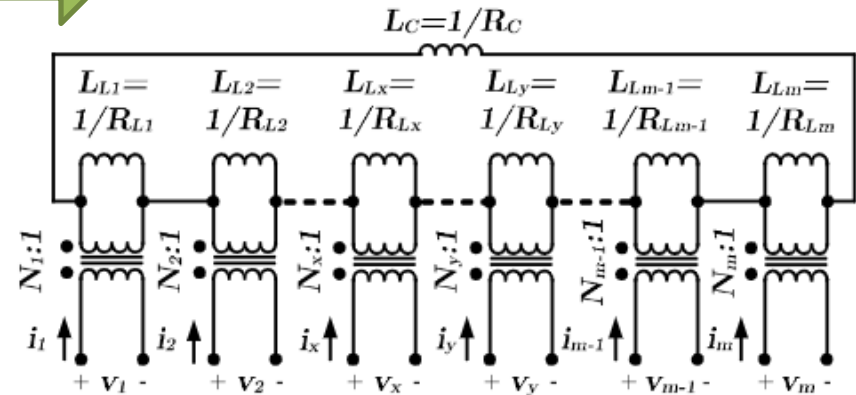
Inductance Matrix Model



Reluctance Model



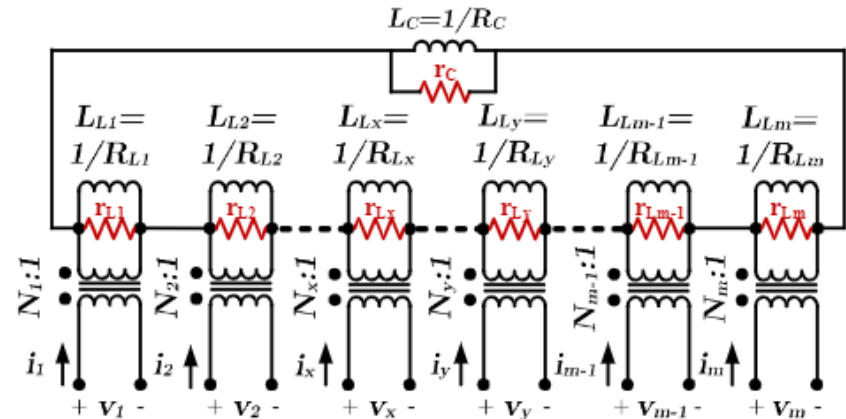
Permeance Model



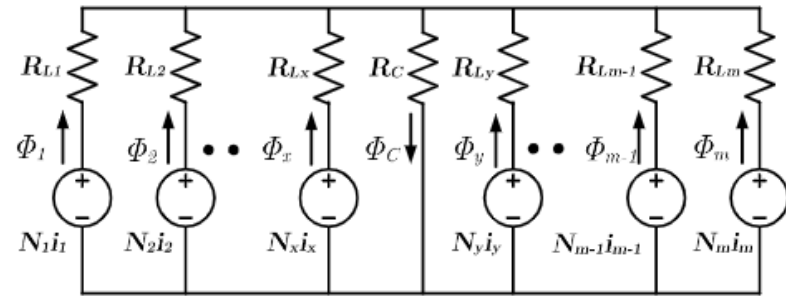
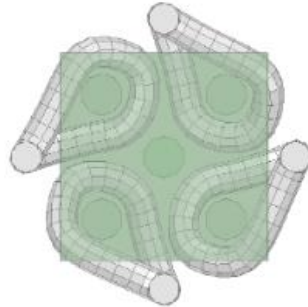
Advantage of the Permeance Model

- Simple
- Intuitive
- No coupled inductors
- Explicit design equations
- Capability of capturing core loss

Permeance Model with Core Loss

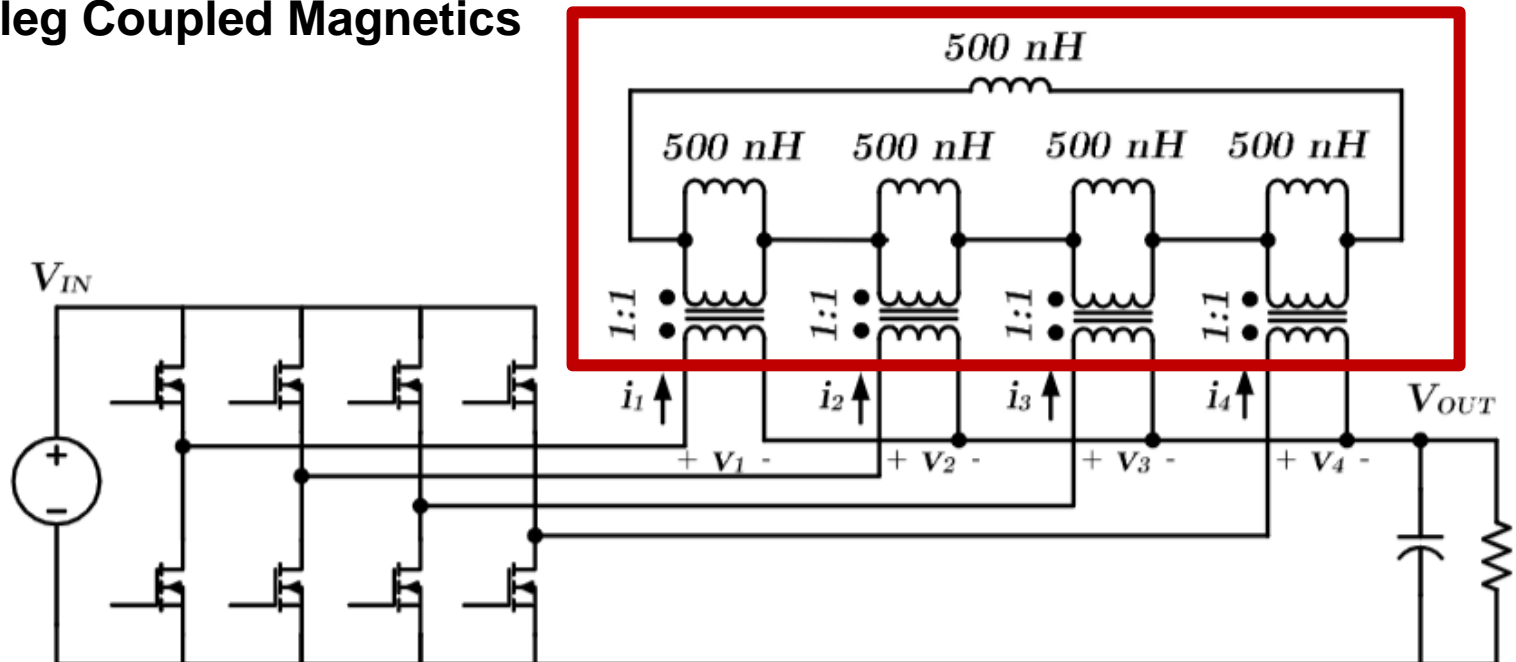


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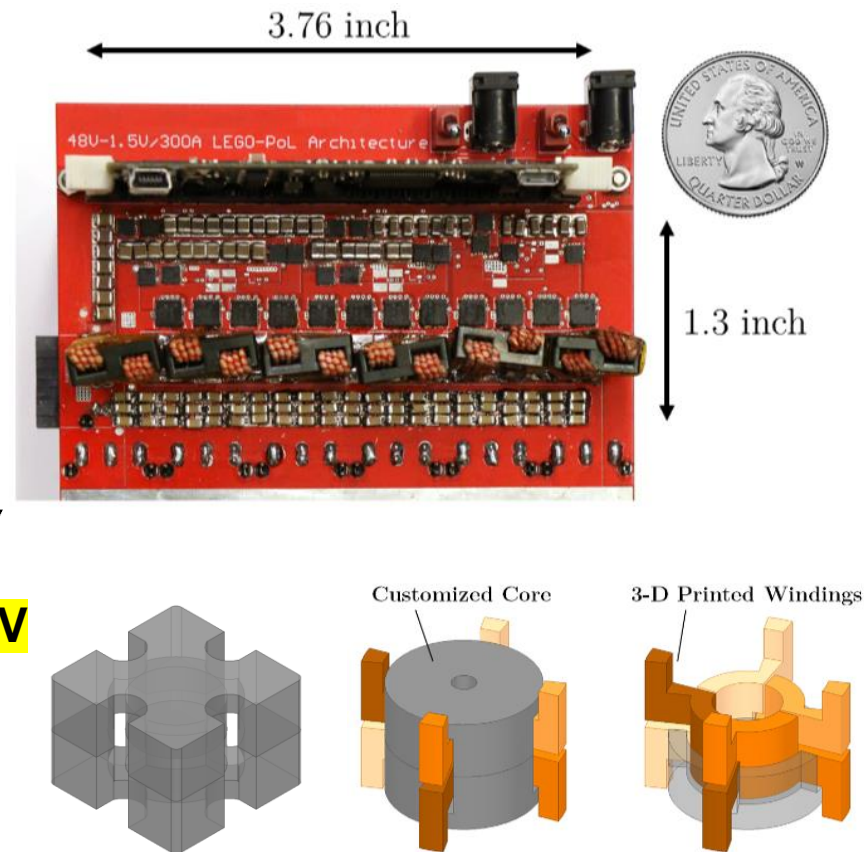
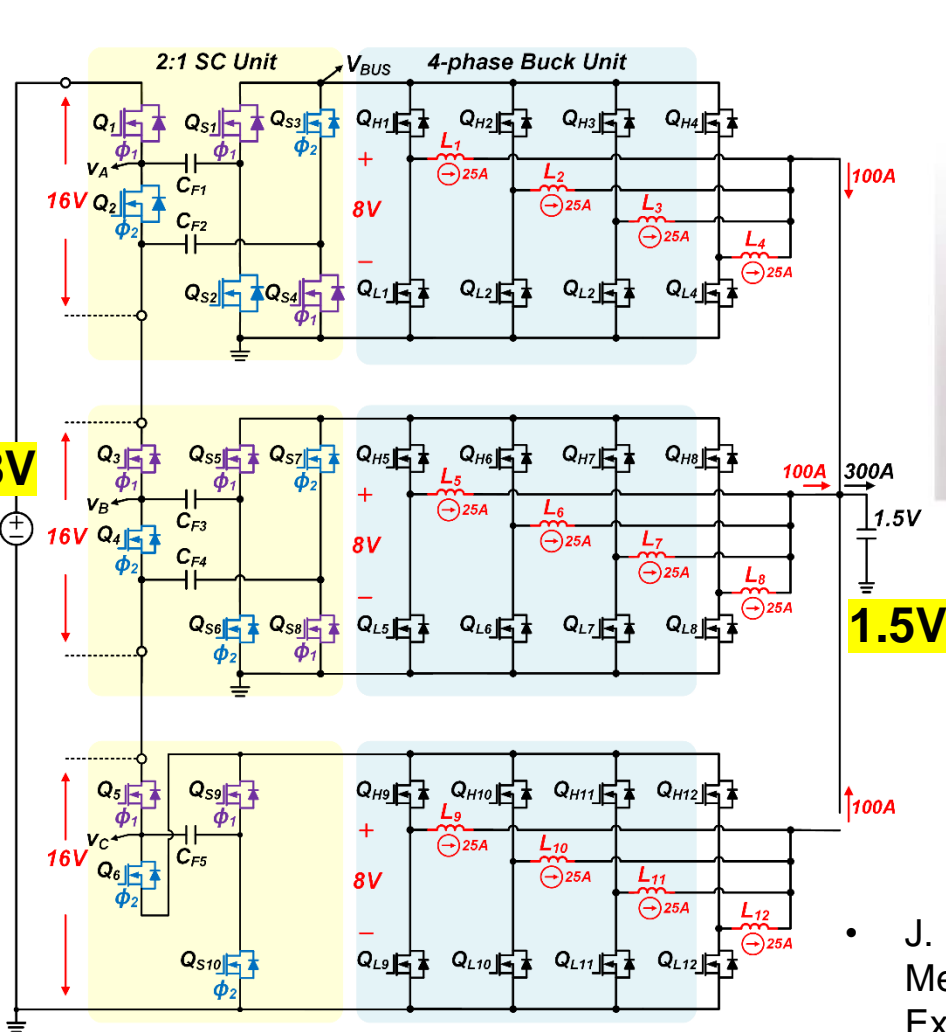


↕ Topological duality

Multileg Coupled Magnetics

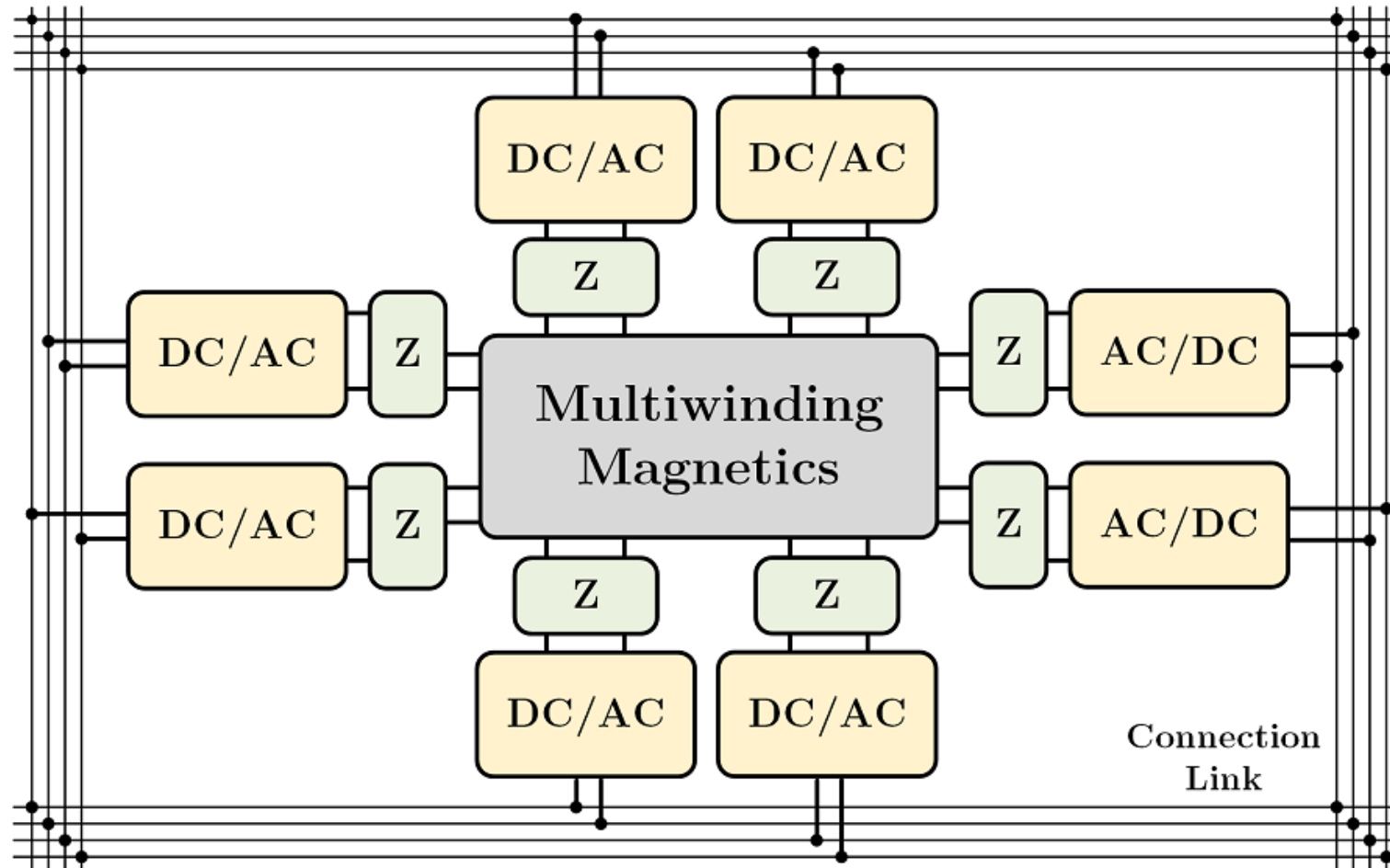


Hybrid Converter with Coupled Magnetics

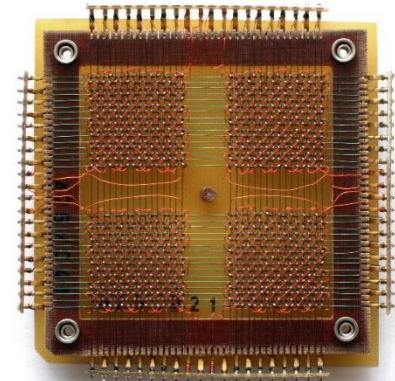
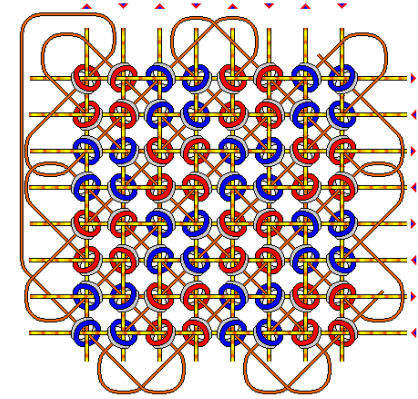
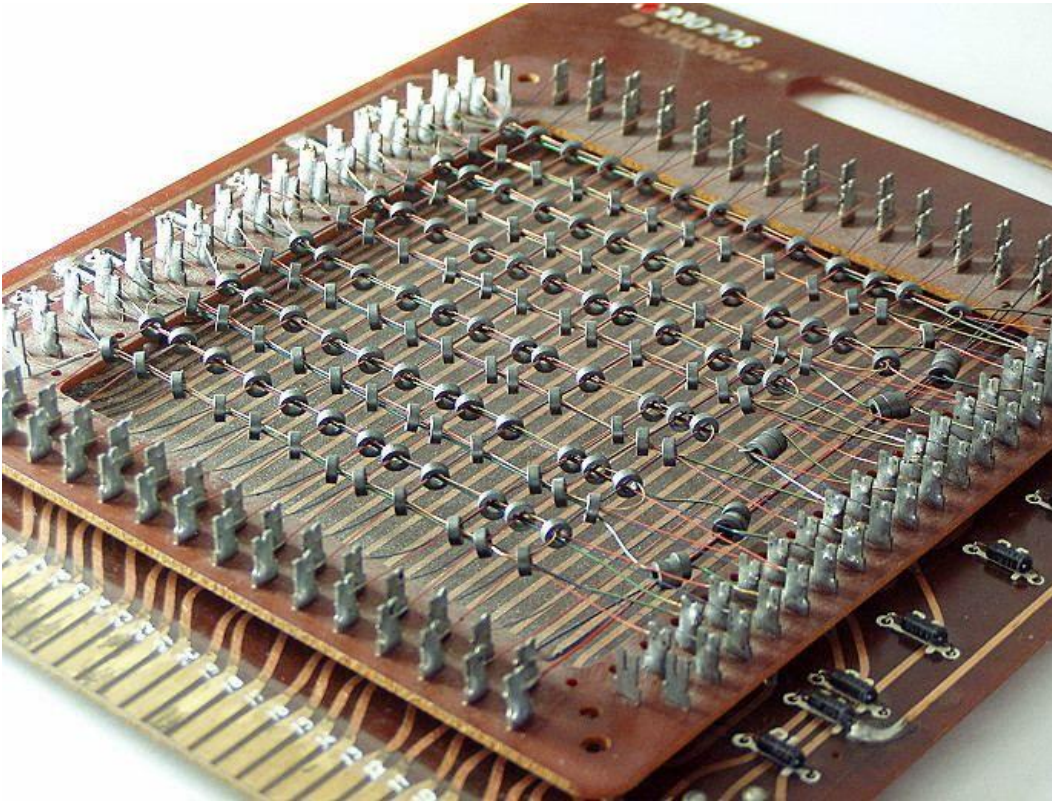


- J. Baek, et al., "LEGO-PoL: A 93.1% 54V-1.5V 300A MergedTwo-Stage Hybrid Converter with a Linear Extendable Group Operated Point-of-Load (LEGO-PoL) Architecture," COMPEL 2019.

Towards a MIMO Magnetic Energy Processor



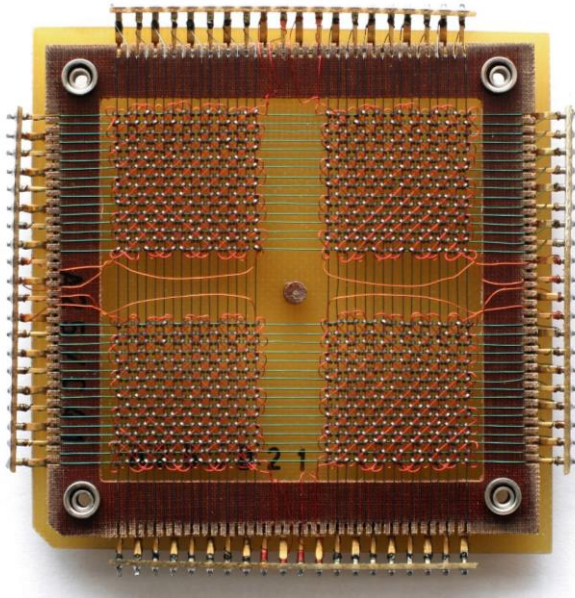
A Magnetic Memory in 1960s



- A 32 x 32 core memory storing 1024 bits of data
- Instead of processing information, we process energy

Exciting Opportunities for Power Electronics & Magnetics

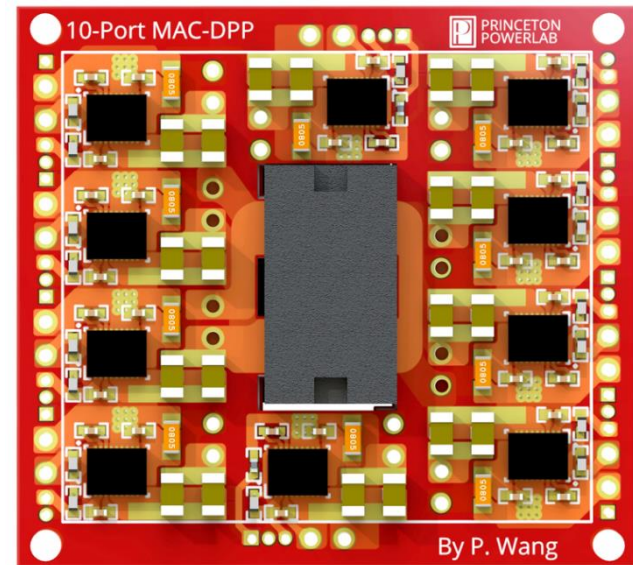
Information Processing



10101
01010
10101



Energy Processing



32 x 32 Magnetic Memory

10-Port MIMO Power Converter

More topologies and designs to be investigated!

Princeton Power Electronics Research Group



Research Sponsors and Collaborators



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